

LED Driver LSI with Step-up Charge Pump Control Circuit

FEATURES

- 7 x 7 LED Matrix Driver
(Total LED that can be driven = 49)
- Step-up charge pump DC/DC converter : 300 mA
- LDO : 2-ch.
- GPIO : 3-ch.
- GPO : 6-ch. (They are in common with LED driver terminals.)
- SPI interface / I²C interface selectable
- LED drivers (for backlight : 7-ch., for RGB : 3-ch., matrix LED driver : 7 x 7-ch.)
- LED brightness control function with an external illumination sensor
- 55pin Wafer Level Chip Size Package (WLCSP)

DESCRIPTION

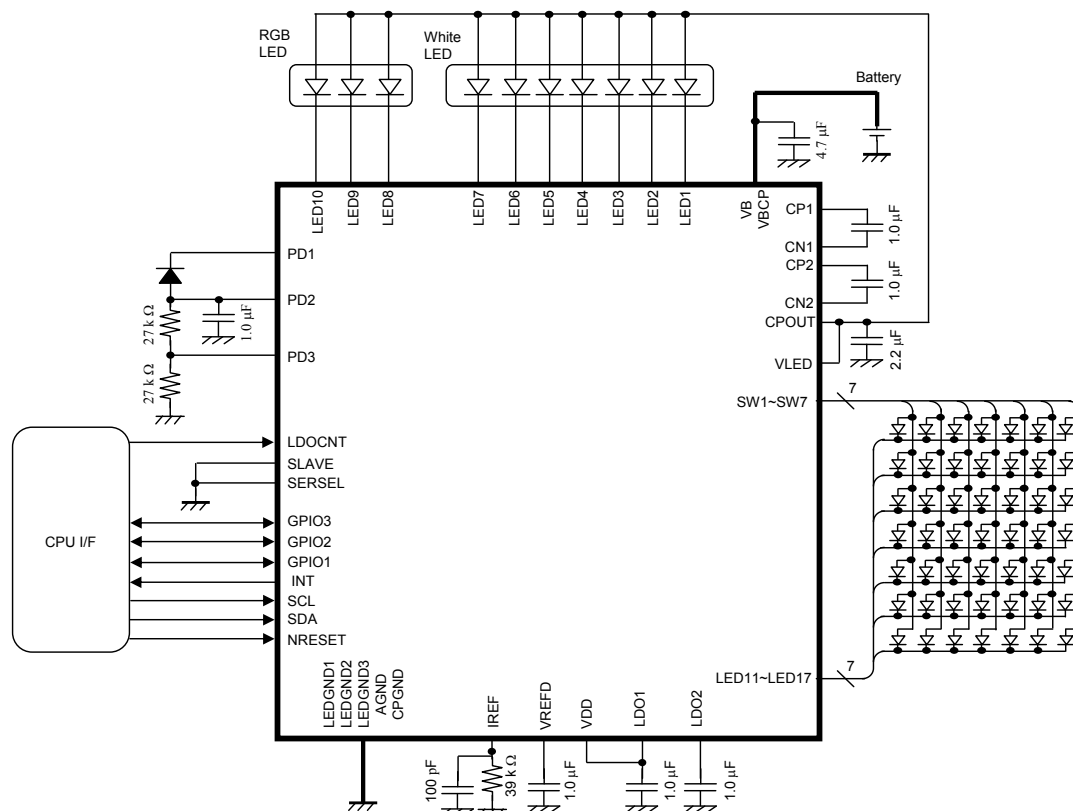
AN32150B is a LED driver and a light intensity controller. It can drive up to 7 channels of LCD backlight, 3 channels of RGB LEDs and 7 channels of LED matrix.

Voltage is supplied by a step-up charge pump DC/DC converter.

APPLICATIONS

- Mobile Phone
- Smart Phone
- PCs
- Game Consoles
- Home Appliances etc.

TYPICAL APPLICATION



Note)

The application circuit is an example. The operation of the mass production set is not guaranteed. Sufficient evaluation and verification is required in the design of the mass production set. The Customer is fully responsible for the incorporation of the above illustrated application circuit in the design of the equipment.

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ABSOLUTE MAXIMUM RATINGS

| Parameter | Symbol | Rating | Unit | Note |
|--------------------------------|---|---------------|------|------|
| Supply voltage | $V_{B_{MAX}}$ | 6.0 | V | *1 |
| | $V_{LED_{MAX}}$ | 6.5 | V | *1 |
| | $V_{DD_{MAX}}$ | 4.3 | V | *1 |
| Operating ambience temperature | T_{opr} | – 30 to + 85 | °C | *2 |
| Operating junction temperature | T_j | – 30 to + 125 | °C | *2 |
| Storage temperature | T_{stg} | – 55 to + 125 | °C | *2 |
| Input Voltage Range | GPIO1, GPIO2, GPIO3, PD2, PD3, SERSEL, SLAVE, SCL, SDA | – 0.3 to 4.3 | V | — |
| | NRESET, LDOCNT | – 0.3 to 6.0 | V | — |
| Output Voltage Range | PD1 | – 0.3 to 4.3 | V | — |
| | LDO1, LDO2, INT | – 0.3 to 6.0 | V | — |
| | SW1, SW2, SW3, SW4, SW5, SW6, SW7, LED1, LED2, LED3, LED4, LED5, LED6, LED7, LED8, LED9, LED10, LED11, LED12, LED13, LED14, LED15, LED16, LED17 | – 0.3 to 6.5 | V | — |
| ESD | HBM | 1.0 to 1.5 | kV | — |

Note) This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteeable as it is higher than our stated recommended operating range. When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

*1: $V_{B_{MAX}} = V_{BCP} = V_B$, $V_{DD_{MAX}} = V_{DD}$, $V_{LED_{MAX}} = V_{LED}$

The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

*2: Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for $T_a = 25^\circ\text{C}$.

POWER DISSIPATION RATING

| PACKAGE | θ_{JA} | $P_D (T_a=25^\circ\text{C})$ | $P_D (T_a=85^\circ\text{C})$ |
|--|---------------|------------------------------|------------------------------|
| 55 pin Wafer Level Chip Size Package (WLCSP) | 120.02 °C /W | 0.833 W | 0.333 W |

Note) For the actual usage, please refer to the P_D - T_a characteristics diagram in the package specification, follow the power supply voltage, load and ambient temperature conditions to ensure that there is enough margin and the thermal design does not exceed the allowable value.



CAUTION

Although this LSI has built-in ESD protection circuit, it may still sustain permanent damage if not handled properly. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates.

RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Note |
|----------------------|---|-------|------|------------|------|------|
| Supply voltage range | VB | 3.1 | 3.6 | 4.6 | V | *1 |
| | VLED | 3.1 | 4.5 | 5.8 | V | *1 |
| | VDD | 1.7 | 1.85 | 3.2 | V | *1 |
| Input Voltage Range | GPIO1, GPIO2, GPIO3, PD2, PD3, SERSEL, SLAVE, SCL, SDA | - 0.3 | — | VDD + 0.3 | V | *2 |
| | NRESET, LDOCNT | - 0.3 | — | VB + 0.3 | V | *2 |
| Output Voltage Range | PD1 | - 0.3 | — | VDD + 0.3 | V | *2 |
| | LDO1, LDO2, INT | - 0.3 | — | VB + 0.3 | V | *2 |
| | SW1, SW2, SW3, SW4, SW5, SW6, SW7, LED1, LED2, LED3, LED4, LED5, LED6, LED7, LED8, LED9, LED10, LED11, LED12, LED13, LED14, LED15, LED16, LED17 | - 0.3 | — | VLED + 0.3 | V | *2 |
| | | | | | | |

Note) *1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

Do not apply external currents and voltages to any pin not specifically mentioned.

Voltage values, unless otherwise specified, are with respect to GND. GND is voltage for AGND, CPGND, LEDGND1, LEDGND2 and LEDGND3.

VDD is voltage for VDD. VB is voltage for VB and VBCP. VLED is voltage for VLED.

*2: (VDD + 0.3) V must not exceed 4.3 V. (VB + 0.3) V must not exceed 6 V.

(VLED + 0.3) V must not exceed 6.5 V.

ELECTRICAL CHARACTERISTICS

VB = VBCP = 3.6 V, VLED = 4.5 V, VDD = 1.85 V

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|--------|--|--------|-----|-----|------|------|
| | | | Min | Typ | Max | | |
| Current consumption | | | | | | | |
| Current consumption (1) at OFF mode | ICC1 | VB = 4.6 V LDOCNT = Low | — | 0 | 1 | μA | — |
| Current consumption (2) at LDO1 and LDO2 normal mode | ICC2 | LDO1 to 2PS = [0] (LDO1, 2 normal mode) LDO1ON = [1] (LDO1 ON) VB = 4.6 V LDOCNT = High | — | 130 | 300 | μA | — |
| Current consumption (3) at LDO1 OFF mode, LDO2 power save mode | ICC3 | LDO2 PS = [1] (LDO2 power save mode) LDO1ON = [0] (LDO1 OFF) VB = 4.6 V LDOCNT = High | — | 10 | 25 | μA | — |
| Current consumption (4) at VB through mode, LDO1 OFF mode, LDO2 power save mode | ICC4 | LDO2 PS = [1] (LDO2 power save mode) LDO1ON = [0] (LDO1 OFF) VB = 4.6 V LDOCNT = High VB through mode I _{CPOUT} = 0 mA LED10ON = [1] (Current 0) | — | 1.0 | 3.0 | mA | — |
| Current consumption (5) at charge pump 1.5× (600 kHz operating) mode, LDO1 OFF mode, LDO2 power save mode | ICC5 | LDO2 PS = [1] (LDO2 power save mode) LDO1ON = [0] (LDO1 OFF) VB = 3.1 V LDOCNT = High LED10ON = [1] (current 0) Charge Pump ON, 1.5×, 600 kHz operating mode I _{CPOUT} = 0 mA | — | 2.0 | 5.0 | mA | — |

ELECTRICAL CHARACTERISTICS (continued)

VB = VBCP = 3.6 V, VLED = 4.5 V, VDD = 1.85 V

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|--------|--|--------|------|------|------|------|
| | | | Min | Typ | Max | | |
| Current consumption | | | | | | | |
| Current consumption (6) at charge pump 1.5× (1.2 MHz operating) mode, LDO1 OFF mode, LDO2 power save mode | ICC6 | LDO2 PS = [1] (LDO2 power save mode) LDO1ON = [0] (LDO1 OFF) VB = 3.1 V LDOCNT = High LED10ON = [1] (current 0) Charge Pump ON, 1.5×, 1.2 MHz operating mode I _{CPOUT} = 0 mA | — | 5.0 | 9.0 | mA | — |
| Reference voltage | | | | | | | |
| Output voltage | VREF | VB = 3.1 V to 4.6 V | 1.21 | 1.24 | 1.27 | V | — |
| Voltage regulator (LDO1) normal mode Ioutmax = −100 mA | | | | | | | |
| Output voltage (1) 1.85 V mode | VL11 | VB = 3.1 V to 4.6 V I _{LDO1} = −10 μA to −100 mA | 1.79 | 1.85 | 1.91 | V | — |
| Output voltage (2) 2.85 V mode | VL12 | VB = 3.1 V to 4.6 V I _{LDO1} = −10 μA to −100 mA | 2.76 | 2.85 | 2.94 | V | — |
| Short circuit protection current (1) 1.85 V mode | IPT11 | LDOCNT = High V _{LDO1} = 0 V | 20 | 50 | 150 | mA | — |
| Short circuit protection current (2) 2.85 V mode | IPT12 | LDOCNT = High V _{LDO1} = 0 V | 20 | 50 | 150 | mA | — |
| Ripple rejection (1) 1.85 V mode | PSL11 | VB = 3.6 V + 0.2 V[p-p] f = 1 kHz I _{LDO1} = −50 mA PSL11 = 20 log(acV _{LDO1} / 0.2) | — | −70 | −60 | dB | — |
| Ripple rejection (2) 1.85 V mode | PSL12 | VB = 3.6 V + 0.2 V[p-p] f = 10 kHz I _{LDO1} = −50 mA PSL12 = 20 log(acV _{LDO1} / 0.2) | — | −60 | −50 | dB | — |
| Ripple rejection (3) 2.85 V mode | PSL13 | VB = 3.6 V + 0.2 V[p-p] f = 1 kHz I _{LDO1} = −50 mA PSL13 = 20 log(acV _{LDO1} / 0.2) | — | −70 | −60 | dB | — |
| Ripple rejection (4) 2.85 V mode | PSL14 | VB = 3.6 V + 0.2 V[p-p] f = 10 kHz I _{LDO1} = −50 mA PSL14 = 20 log(acV _{I_{LDO1}} / 0.2) | — | −60 | −50 | dB | — |

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|--------|--|--------|------|------|------|------|
| | | | Min | Typ | Max | | |
| Voltage regulator (LDO1) power save mode : Ioutmax = – 15 mA (Ioutmax = – 5 mA at 2.85 V setting) | | | | | | | |
| Output voltage (1) | VLPS11 | VB = 3.1 V to 4.6 V ILDO1 = – 10 μA to – 15 mA | 1.79 | 1.85 | 1.91 | V | — |
| Output voltage (2) | VLPS12 | VB = 3.1 V to 4.6 V ILDO1 = – 10 μA to – 5 mA | 2.76 | 2.85 | 2.94 | V | — |
| Voltage regulator (LDO2) normal mode Ioutmax = – 100 mA | | | | | | | |
| Output voltage | VL2 | VB = 3.1 V to 4.6 V ILDO2 = – 10 μA to – 100 mA | 2.76 | 2.85 | 2.94 | V | — |
| Short circuit protection current | IPT2 | LDOCNT = High VLDO2 = 0 V | 20 | 50 | 150 | mA | — |
| Ripple rejection (1) | PSL21 | VB = 3.6 V + 0.2 V[p-p] f = 1 kHz ILDO2 = – 50 mA PSL21 = 20 log(acVLDO2 / 0.2) | — | – 70 | – 60 | dB | — |
| Ripple rejection (2) | PSL22 | VB = 3.6 V +0.2 V[p-p] f = 10 kHz ILDO2 = – 50 mA PSL22 = 20 log(acVLDO2 / 0.2) | — | – 60 | – 50 | dB | — |
| Voltage regulator (LDO2) power save mode Ioutmax = – 5 mA | | | | | | | |
| Output voltage | VLPS2 | VB = 3.1 V to 4.6 V ILDO2 = – 10 μA to – 5 mA | 2.76 | 2.85 | 2.94 | V | — |

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|-------------------------------|--------|--|--------|--------|--------|------|------|
| | | | Min | Typ | Max | | |
| Charge pump DC/DC converter | | | | | | | |
| Oscillator frequency | FDC1 | VB = 3.1 V to 4.6 V | 1.92 | 2.40 | 2.88 | MHz | — |
| VB through switch | | | | | | | |
| Resistance at switch ON | RVBS | VB = 4.5 V ICPOUT = − 30 mA RVBS = (VVB _{CP} − VCP _{OUT}) / 30 mA | — | 0.6 | 1 | Ω | — |
| SCAN switch | | | | | | | |
| Resistance at switch ON | RSCAN | VLED = 4.5 V ISW1 to ISW7 = 20 mA RSCAN = VSW1 to VSW7 / 20 mA | — | 1 | 2 | Ω | — |
| Current regulator (LED1 to 7) | | | | | | | |
| Output current (1) | IBL1 | At 31.750 mA setting VLED1 to VLED7 = 1 V IBL1 = ILED1 to ILED7 | 30.132 | 31.718 | 33.304 | mA | *1 |
| Output current (2) | IBL2 | At 1 mA setting VLED1 to VLED7 = 1 V IBL2 = ILED1 to ILED7 | 0.948 | 0.998 | 1.048 | mA | *1 |
| Current step | IBSTEP | Minimum current step | 0 | 125 | 250 | μA | — |
| Off leak current | IBLOFF | OFF setting VLED1 to VLED7 = 4.5 V IBLOFF = ILED1 to ILED7 | — | — | 1 | μA | — |
| Error between channels | IBLCH | At 16 mA setting Current error between each channel and the median of LED1 to LED7 | − 5 | — | 5 | % | — |

Note) *1 : Allowable value at the time when the recommended parts (ERJ2RHD393X) is connected to IREF.

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ °C} \pm 2\text{ °C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---------------------------------|----------|--|--------|--------|--------|------|------|
| | | | Min | Typ | Max | | |
| Current regulator (LED8 to 10) | | | | | | | |
| Output current (1) | IRGB1 | At 31.750 mA setting V_{LED8} to V_{LED10} = 1 V $IRGB1 = I_{LED8}$ to I_{LED10} | 30.087 | 31.671 | 33.254 | mA | *1 |
| Output current (2) | IRGB2 | At 1 mA setting V_{LED8} to V_{LED10} = 1 V $IRGB2 = I_{LED8}$ to I_{LED10} | 0.946 | 0.996 | 1.046 | mA | *1 |
| Current step | IRGBSTEP | Minimum current step | 0 | 125 | 250 | μA | — |
| Off leak current | IRGBOFF | OFF setting V_{LED8} to V_{LED10} = 4.5 V $IRGBOFF = I_{LED8}$ to I_{LED10} | — | — | 1 | μA | — |
| Error between channels | IRGBCH | At 16 mA setting Current error between each channel and the median of LED8 to LED10 | −5 | — | 5 | % | — |
| Current regulator (LED11 to 17) | | | | | | | |
| Output current (1) | IMX1 | At 1 mA setting V_{LED11} to V_{LED17} = 1 V $IMX1 = I_{LED11}$ to I_{LED17} | 0.943 | 0.993 | 1.043 | mA | *1 |
| Output current (2) | IMX2 | At 2 mA setting V_{LED11} to V_{LED17} = 1 V $IMX2 = I_{LED11}$ to I_{LED17} | 1.891 | 1.990 | 2.090 | mA | *1 |
| Output current (3) | IMX3 | At 4 mA setting V_{LED11} to V_{LED17} = 1 V $IMX3 = I_{LED11}$ to I_{LED17} | 3.768 | 3.966 | 4.164 | mA | *1 |
| Output current (4) | IMX4 | At 8 mA setting V_{LED11} to V_{LED17} = 1 V $IMX4 = I_{LED11}$ to I_{LED17} | 7.558 | 7.956 | 8.354 | mA | *1 |
| Output current (5) | IMX5 | At 15 mA setting V_{LED11} to V_{LED17} = 1 V $IMX5 = I_{LED11}$ to I_{LED17} | 14.172 | 14.918 | 15.663 | mA | *1 |
| Off leak current | IMXOFF | OFF setting V_{LED11} to V_{LED17} = 4.5 V $IMXOFF = I_{LED11}$ to I_{LED17} | — | — | 1 | μA | — |
| Error between channels | IMXCH | At 15 mA setting Current error between each channel and the median of LED11 to LED17 | − 5 | — | 5 | % | — |

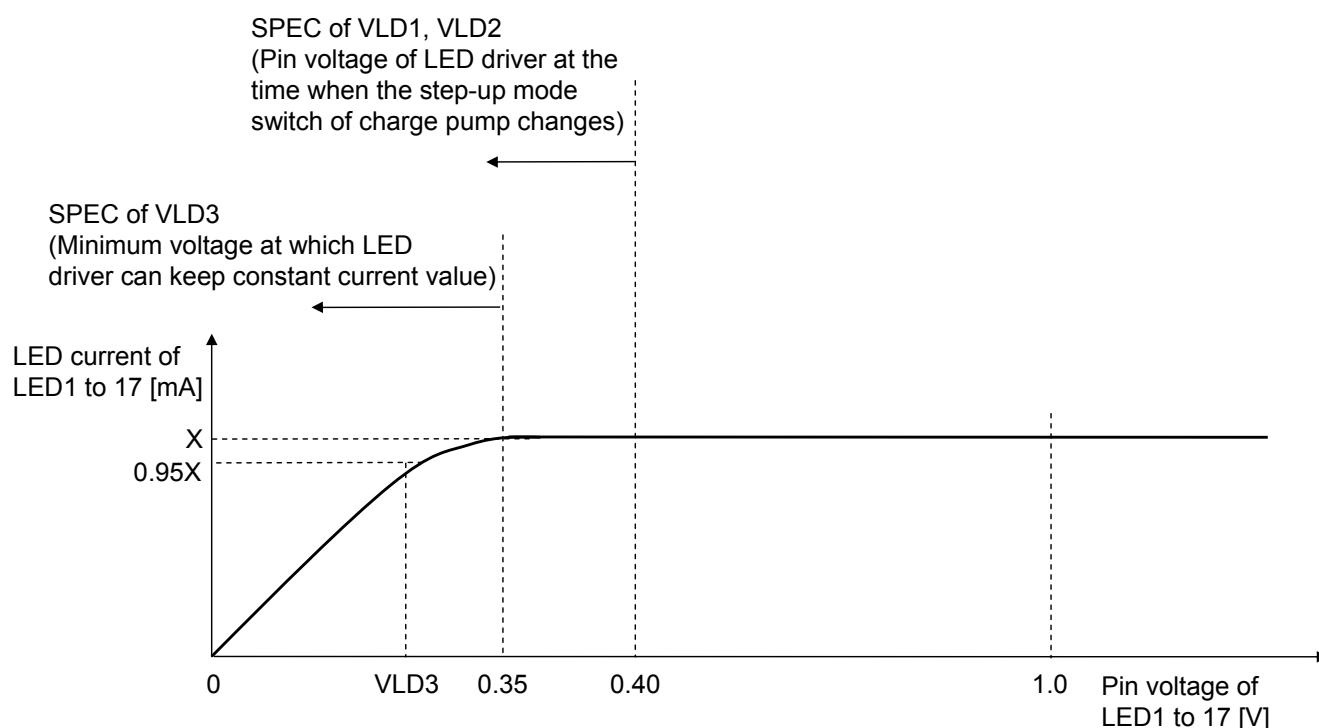
Note) *1 : Allowable value at the time when the recommended parts (ERJ2RHD393X) is connected to IREF.

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|--------|---|--------|------|------|------|------|
| | | | Min | Typ | Max | | |
| Overvoltage detection | | | | | | | |
| Detection voltage | VOV | Charge pump DC/DC overvoltage detection | 5.3 | 5.5 | 5.7 | V | — |
| Step-up mode switch of charge pump | | | | | | | |
| Detection voltage (1) | VLD1 | LED1 to LED7 pin voltage at the time when the step-up mode switch of charge pump changes | — | 0.35 | 0.40 | V | — |
| Detection voltage (2) | VLD2 | LED8, 9 and 10 pin voltage at the time when the step-up mode switch of charge pump changes | — | 0.35 | 0.40 | V | — |
| Minimum voltage at which LED driver can keep constant current value | | | | | | | |
| Minimum voltage at which LED driver can keep constant current value | VLD3 | 95% LED current value at the time when LED1 to LED17 pin voltage is set to 1 V. Minimum value of LED1 to LED17 pin voltage | — | 0.20 | 0.35 | V | — |



ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ °C} \pm 2\text{ °C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|--|--------|---|---------------|-----|---------------|---------------|------|
| | | | Min | Typ | Max | | |
| GPIO I/F | | | | | | | |
| High-level input voltage range (1) at 1.85 V mode operation | VIH1 | High-level recognition voltage of GPIO1 to 3. IOVSEL1 to 3 = [1] (Output voltage LDO1 level setting) LDO1VSEL = [0] | 1.5 | — | LDO1 + 0.3 | V | — |
| Low-level input voltage range (1) at 1.85 V mode operation | VIL1 | Low-level recognition voltage of GPIO1 to 3. IOVSEL1 to 3 = [1] (Output voltage LDO1 level setting) LDO1VSEL = [0] | − 0.3 | — | 0.4 | V | — |
| High-level input voltage range (2) at 2.85 V mode operation | VIH2 | High-level recognition voltage of GPIO1 to 3. LDO1VSEL = [1] | 2.3 | — | LDO1 + 0.3 | V | — |
| Low-level input voltage range (2) at 2.85 V mode operation | VIL2 | Low-level recognition voltage of GPIO1 to 3. LDO1VSEL = [1] | − 0.3 | — | 0.6 | V | — |
| High-level input current | IIH1 | V_{GPIO1} to $V_{GPIO3} = 2.85\text{ V}$ $IIH1 = I_{GPIO1}$ to I_{GPIO3} | — | 0 | 1 | μA | — |
| Low-level input current | IIL1 | V_{GPIO1} to $V_{GPIO3} = 0\text{ V}$ $IIL1 = I_{GPIO1}$ to I_{GPIO3} | — | 0 | 1 | μA | — |
| High-level output voltage (1) | VOH1 | V_{GPIO1} to $V_{GPIO3} = -2\text{ mA}$ IOVSEL1 to 3 = [0] (Output voltage LDO2 level setting) | LDO2 × 0.8 | — | — | V | — |
| Low-level output voltage (1) | VOL1 | I_{GPIO1} to $I_{GPIO3} = 2\text{ mA}$ IOVSEL1 to 3 = [0] (Output voltage LDO2 level setting) | — | — | LDO2 × 0.2 | V | — |
| High-level output voltage (2) | VOH2 | I_{GPIO1} to $I_{GPIO3} = -2\text{ mA}$ IOVSEL1 to 3 = [1] (Output voltage LDO1 level setting) | LDO1 × 0.8 | — | — | V | — |
| Low-level output voltage (2) | VOL2 | I_{GPIO1} to $I_{GPIO3} = 2\text{ mA}$ IOVSEL1 ~ 3 = [1] (Output voltage LDO1 level setting) | — | — | LDO1 × 0.2 | V | — |
| Pull-down resistance | RPD | I_{GPIO1} to $I_{GPIO3} = 5\text{ }\mu\text{A}$ $RPD = V_{GPIO1}$ to $V_{GPIO3} / 5\text{ }\mu\text{A}$ | 60 | 110 | 210 | kΩ | — |

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|--------------------------------|--------|---|--------|-----|----------|------|------|
| | | | Min | Typ | Max | | |
| LDOCNT | | | | | | | |
| High-level input voltage range | VIH3 | High-level recognition voltage | 1.6 | — | VB + 0.3 | V | — |
| Low-level input voltage range | VIL3 | Low-level recognition voltage | − 0.3 | — | 0.4 | V | — |
| High-level input current | IIH2 | V _{LDOCNT} = 3.6 V | — | 0 | 1 | μA | — |
| Low-level input current | IIL2 | V _{LDOCNT} = 0 V | — | 0 | 1 | μA | — |
| NRESET | | | | | | | |
| High-level input voltage range | VIH4 | High-level recognition voltage | 1.5 | — | VB + 0.3 | V | — |
| Low-level input voltage range | VIL4 | Low-level recognition voltage | − 0.3 | — | 0.6 | V | — |
| High-level input current | IIH3 | V _{NRESET} = 3.6 V | — | 0 | 1 | μA | — |
| Low-level input current | IIL3 | V _{NRESET} = 0 V | — | 0 | 1 | μA | — |
| INT | | | | | | | |
| ON resistance | RINTON | I _{INT} = 5 mA RINTON = V _{INT} / 5 mA | — | — | 50 | Ω | — |

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|----------------------------|------------------|---|-----------|-----|----------------|------|------|
| | | | Min | Typ | Max | | |
| I ² C I/F | | | | | | | |
| High-level input voltage | VIH5 | High-level recognition voltage of SDA, SCL | 0.7 × VDD | — | VDD + 0.5, 3.2 | V | *2 |
| Low-level input voltage | VIL5 | Low-level recognition voltage of SDA, SCL | − 0.5 | — | 0.3 × VDD | V | — |
| Low-level output voltage 1 | VOL3 | VDD > 2 V I _{SDA} = 3 mA | 0 | — | 0.4 | V | — |
| Low-level output voltage 2 | VOL4 | VDD < 2 V I _{SDA} = 3 mA | 0 | — | 0.2 × VDD | V | — |
| Input current each I/O pin | li | V _{SDA} , V _{SCL} = 0.1 V to 2.88 V | − 10 | 0 | 10 | μA | — |
| SCL clock frequency | f _{SCL} | — | 0 | — | 400 | kHz | — |
| Light Intensity Control | | | | | | | |
| PD1 pin ON resistance | RPD1ON | — | — | — | 100 | Ω | — |
| PD3 pin ON resistance | RPD3ON | — | — | — | 50 | Ω | — |
| A/D converted value (1) | AD1 | V _{PD2} = VLPS2 / 256 Read value of the register, ADC_DATA[9:2] | — | 1 | 5 | LSB | — |
| A/D converted value (2) | AD2 | V _{PD2} = VLPS2 × 128 / 256 Read value of the register, ADC_DATA[9:2] | 124 | 128 | 132 | LSB | — |
| A/D converted value (3) | AD3 | V _{PD2} = VLPS2 × 255 / 256 Read value of the register, ADC_DATA[9:2] | 251 | 255 | — | LSB | — |

Note) *2 : Maximum value of High-level input voltage range is the lower one of ($V_{DD} + 0.5\text{ V}$) and 3.2 V .

ELECTRICAL CHARACTERISTICS (continued)

VB = VBCP = 3.6 V, VLED = 4.5 V, VDD = 1.85 V

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|--|--------|---|--------|-----|-----|------|------|
| | | | Min | Typ | Max | | |
| Current consumption | | | | | | | |
| Current consumption (1) at OFF mode | ICC1 | VB = 3.1 V to 4.6 V LDOCNT = Low | — | 0 | — | μA | *3 |
| Current consumption (2) at LDO1 and LDO2 normal mode | ICC2 | LDO1 to 2PS = [0] (LDO1, 2 normal mode) LDO1ON = [1] (LDO1 ON) VB = 3.1 V to 4.6 V LDOCNT = High | — | 130 | — | μA | *3 |
| Current consumption (3) at LDO1 OFF mode, LDO2 power save mode | ICC3 | LDO2 PS = [1] (LDO2 power save mode) LDO1ON = [0] (LDO1 OFF) VB = 3.1 V to 4.6 V LDOCNT = High | — | 10 | — | μA | *3 |
| Current consumption (4) at VB through mode, LDO1 OFF mode, LDO2 power save mode | ICC4 | LDO2 PS = [1] (LDO2 power save mode) LDO1ON = [0] (LDO1 OFF) VB = 3.1 V to 4.6 V LDOCNT = High VB through mode I _{CPOUT} = 0 mA LED10ON = [1] (Current 0) | — | 1.0 | — | mA | *3 |

Note) *3 : Typical Design Value

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|--------|---|--------|------|-----|------|------|
| | | | Min | Typ | Max | | |
| Voltage regulator (LDO1) power save mode Ioutmax = – 15 mA (Ioutmax = – 5 mA at 2.85 V setting) | | | | | | | |
| Ripple rejection (1) at power save mode | PSL11 | 1.85 V mode VB = 3.6 V + 0.2 V[p-p] f = 1 kHz ILDO1 = – 7.5 mA PSL11 = 20 log(acVLDO1 / 0.2) | — | – 40 | — | dB | *3 |
| Ripple rejection (2) at power save mode | PSL12 | 1.85 V mode VB = 3.6 V + 0.2 V[p-p] f = 10 kHz ILDO1 = – 7.5 mA PSL12 = 20 log(acVLDO1 / 0.2) | — | – 30 | — | dB | *3 |
| Voltage regulator (LDO2) power save mode Ioutmax = – 5 mA | | | | | | | |
| Ripple rejection (1) at power save mode | PSL21 | VB = 3.6 V + 0.2 V[p-p] f = 1 kHz ILDO2 = – 2.5 mA PSL21 = 20 log(acVLDO2 / 0.2) | — | – 40 | — | dB | *3 |
| Ripple rejection (2) at power save mode | PSL22 | VB = 3.6 V + 0.2 V[p-p] f = 10 kHz ILDO2 = – 2.5 mA PSL22 = 20 log(acVLDO2 / 0.2) | — | – 30 | — | dB | *3 |

Note) *3 : Typical Design Value

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|--------|--|------------------------------|-----|-----|------|----------|
| | | | Min | Typ | Max | | |
| I ² C I/F | | | | | | | |
| Hysteresis of Schmitt trigger input 1 | Vhys1 | V _{DD} > 2 V, Hysteresis voltage of SDA, SCL | 0.05 × VDD | — | — | V | *4 *5 |
| Hysteresis of Schmitt trigger input 2 | Vhys2 | V _{DD} < 2 V, Hysteresis voltage of SDA, SCL | 0.1 × VDD | — | — | V | *4 *5 |
| Output fall time from V _{IHmin} to V _{ILmax} | Tof | Bus capacitance : 10 pF to 400 pF I _P ≤ 6 mA (V _{OLmax} = 0.6 V) I _P : Max. sink current | 20 + 0.1 × C _b | — | 250 | ns | *4 *5 |
| Pulse width of spikes which must be suppressed by the input filter | Tsp | — | 0 | — | 50 | ns | *4 *5 |
| Capacitance for each I/O pin | Ci | — | — | — | 10 | pF | *4 *5 |

Note) *4 : The timing of Fast-mode Plus devices in I²C-bus is specified in Page.19. All values referred to V_{IHmin} and V_{ILmax} level.

*5 : These are values checked by design but not production tested.

ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ °C} \pm 2\text{ °C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|--|---------------------|--|------------------------------|-----|-----|------|----------|
| | | | Min | Typ | Max | | |
| I ² C I/F (continued) | | | | | | | |
| Hold time (repeated) | t _{HD:STA} | The first clock pulse is generated after t _{HD:STA} | 0.6 | — | — | μs | *4 *5 |
| Low period of the SCL clock | t _{LOW} | — | 1.3 | — | — | μs | *4 *5 |
| High period of the SCL clock | t _{HIGH} | — | 0.6 | — | — | μs | *4 *5 |
| Set-up time for a repeat START condition | t _{SU:STA} | — | 0.6 | — | — | μs | *4 *5 |
| Data hold time | t _{HD:DAT} | — | 0 | — | 0.9 | μs | *4 *5 |
| Data set-up time | t _{SU:DAT} | — | 100 | — | — | ns | *4 *5 |
| Rise time of both SDA and SCL signals | t _r | — | 20 + 0.1 × C _b | — | 300 | ns | *4 *5 |
| Fall time of both SDA and SCL signals | t _f | — | 20 + 0.1 × C _b | — | 300 | ns | *4 *5 |
| Set-up time of STOP condition | t _{SU:STO} | — | 0.6 | — | — | μs | *4 *5 |
| Bus free time between a STOP and START condition | t _{BUF} | — | 1.3 | — | — | μs | *4 *5 |
| Capacitive load for each bus line | C _b | — | — | — | 400 | pF | *4 *5 |
| Noise margin at the Low-level for each connected device | V _{aL} | — | 0.1 × VDD | — | — | V | *4 *5 |
| Noise margin at the High-level for each connected device | V _{aH} | — | 0.2 × VDD | — | — | V | *4 *5 |

Note) *4 : The timing of Fast-mode Plus devices in I²C-bus is specified in Page.19. All values referred to V_{IHMIN} and V_{ILMAX} level.

*5 : These are values checked by design but not production tested.

ELECTRICAL CHARACTERISTICS (continued)

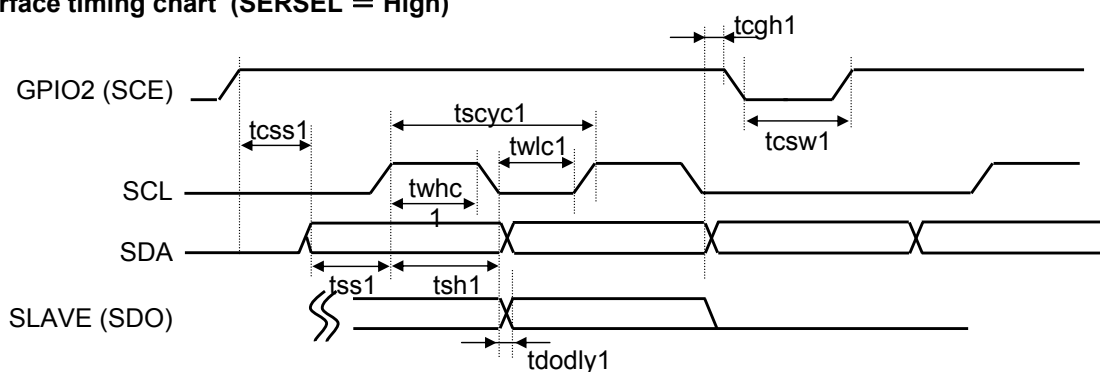
$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ unless otherwise specified

| Parameter | Symbol | Condition | Limits | | | Unit | Note |
|---|---------|----------------|--------|-----|-----|------|------|
| | | | Min | Typ | Max | | |
| SPI interface characteristics (VDD = 1.85 V ± 3%) Reception timing | | | | | | | |
| SCL cycle time | tscyc1 | — | — | 152 | — | ns | *3 |
| SCL cycle time High period | twhc1 | — | — | 70 | — | ns | *3 |
| SCL cycle time Low period | twlc1 | — | — | 70 | — | ns | *3 |
| Serial data setup time | tss1 | — | — | 62 | — | ns | *3 |
| Serial data hold time | tsh1 | — | — | 62 | — | ns | *3 |
| Transmitting and receiving interval | tcswh1 | — | — | 62 | — | ns | *3 |
| Chip enable setup time | tcsh1 | — | — | 5 | — | ns | *3 |
| Chip enable hold time | tcgh1 | — | — | 5 | — | ns | *3 |
| SPI interface characteristics (VDD = 1.85 V ± 3%) Transmission timing | | | | | | | |
| SCL cycle time | tscyc1 | — | — | 152 | — | ns | *3 |
| SCL cycle time High period | twhc1 | — | — | 70 | — | ns | *3 |
| SCL cycle time Low period | twlc1 | — | — | 70 | — | ns | *3 |
| Serial data setup time | tss1 | — | — | 62 | — | ns | *3 |
| Serial data hold time | tsh1 | — | — | 62 | — | ns | *3 |
| Transmitting and receiving interval | tcswh1 | — | — | 62 | — | ns | *3 |
| Chip enable setup time | tcsh1 | — | — | 5 | — | ns | *3 |
| Chip enable hold time | tcgh1 | — | — | 5 | — | ns | *3 |
| DC delay time | tdodly1 | Only read mode | — | 30 | — | ns | *3 |

Note) *3 : Typical Design Value

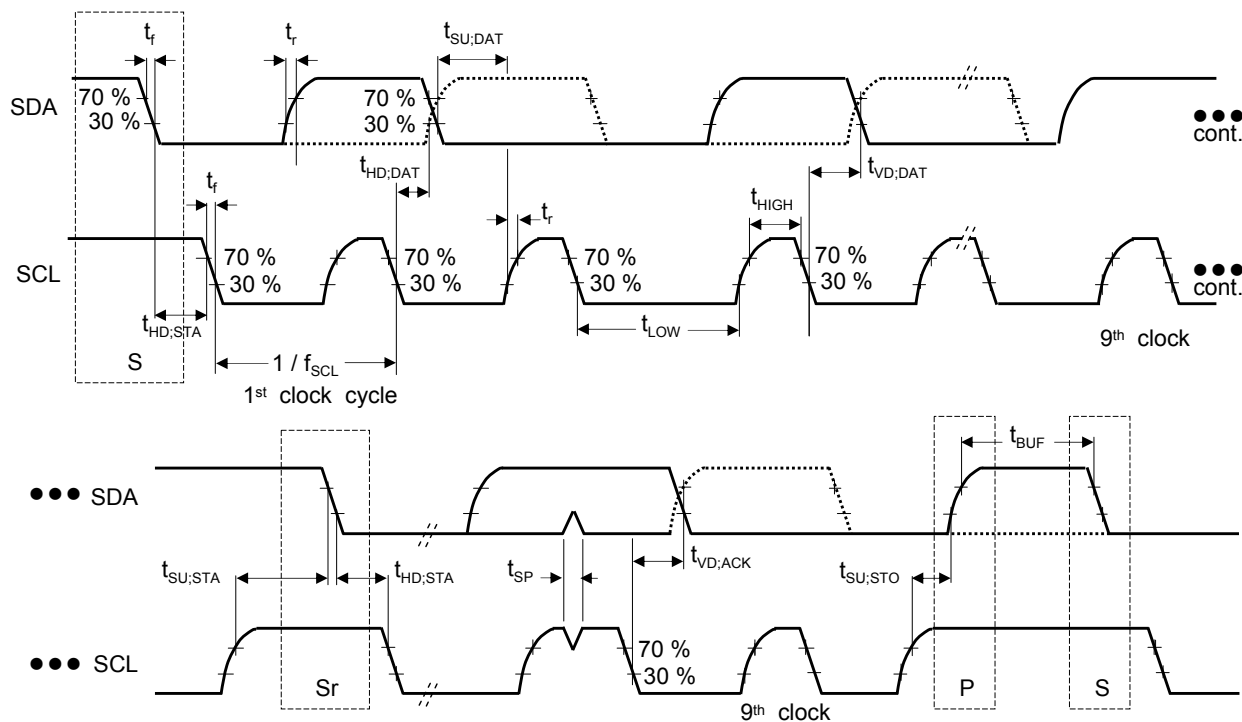
SPI interface timing chart (SERSEL = High)



ELECTRICAL CHARACTERISTICS (continued)

$V_B = V_{BCP} = 3.6\text{ V}$, $V_{LED} = 4.5\text{ V}$, $V_{DD} = 1.85\text{ V}$

Note) $T_a = 25\text{ }^\circ\text{C} \pm 2\text{ }^\circ\text{C}$ unless otherwise specified



$V_{ILMAX} = 0.3 V_{DD}$

$V_{IHMIN} = 0.7 V_{DD}$

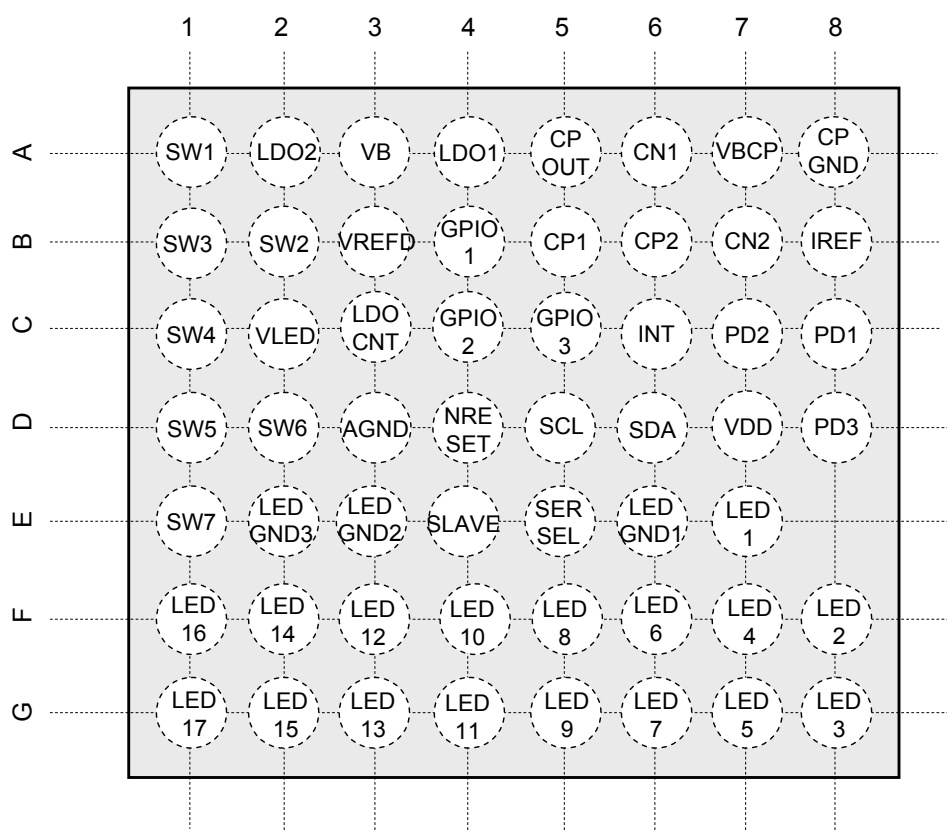
S : START condition

Sr : Repeat START condition

P : STOP condition

PIN CONFIGURATION

TOP VIEW



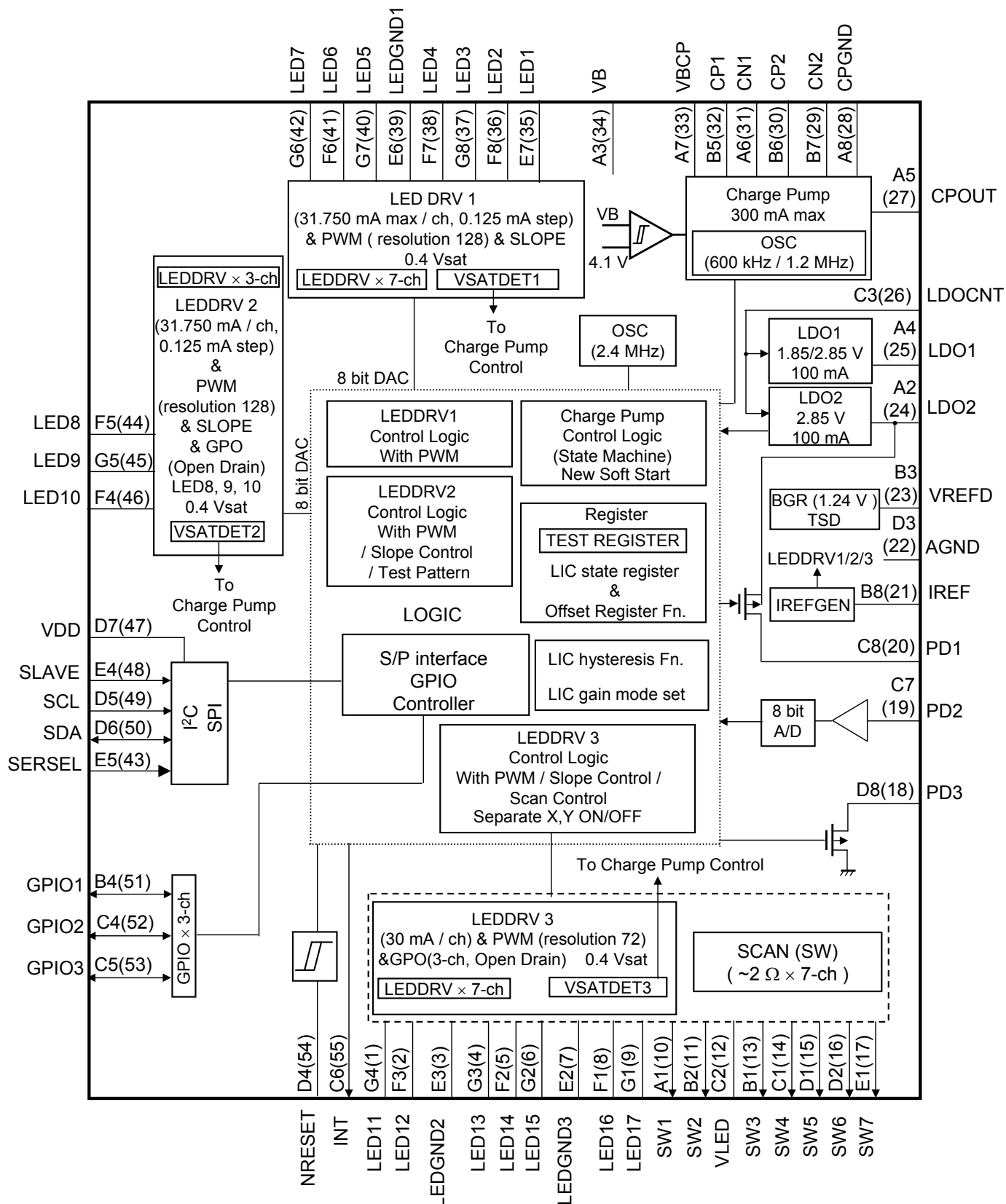
PIN FUNCTIONS

| Pin No. | Pin name | Type | Description | Pin processing at unused |
|---------|----------|----------------|--|---|
| A1 | SW1 | Output | Control switch pin for matrix driver Connected to A column of matrix LED. | Open |
| A2 | LDO2 | Output | LDO2 (2.85 V) output pin | (Required pin) |
| A3 | VB | Power supply | Power supply connection pin for BGR and LDO circuits | (Required pin) |
| A4 | LDO1 | Output | LDO1 (1.85 V / 2.85 V) output pin (Default : 1.85 V output) | (Required pin) |
| A5 | CPOUT | Output | Charge pump output pin (Output pin for VB through SW) | Open |
| A6 | CN1 | Output | Capacitor connection pin for charge pump DC/DC converter | Open |
| A7 | VBCP | Power supply | Power supply connection pin for charge pump DC/DC converter and for through switch | (Required pin) |
| A8 | CPGND | Ground | GND for charge pump DC/DC converter | Connect to GND |
| B1 | SW3 | Output | Control switch pin for matrix driver Connected to C column of matrix LED. | Open |
| B2 | SW2 | Output | Control switch pin for matrix driver Connected to B column of matrix LED. | Open |
| B3 | VREFD | Output | Capacitor connection pin for BGR circuit | (Required pin) |
| B4 | GPIO1 | Input / Output | GPIO input / output port pin (Default input mode with pull-down) | Recommended to connect to GND |
| B5 | CP1 | Output | Capacitor connection pin for charge pump DC/DC converter | Open |
| B6 | CP2 | Output | Capacitor connection pin for charge pump DC/DC converter | Open |
| B7 | CN2 | Output | Capacitor connection pin for charge pump DC/DC converter | Open |
| B8 | IREF | Output | Resistor connection pin for constant current setup | (Required pin) |
| C1 | SW4 | Output | Control switch pin for matrix driver Connected to D column of matrix LED. | Open |
| C2 | VLED | Power supply | Power supply for matrix driver Connected to the output of battery or step-up charge pump DC/DC converter. | Connect to VBAT or CPOUT (Open disabled) |
| C3 | LDOCNT | Input | BGR circuit, ON/OFF control pin of LDO1 and LDO2 | (Required pin) |
| C4 | GPIO2 | Input / Output | GPIO input / output port pin (Default input mode with pull-down) At SERSEL pin = High (SPI mode) : SCE pin | Recommended to connect to GND |
| C5 | GPIO3 | Input / Output | GPIO input / output port pin (Default input mode with pull-down) | Recommended to connect to GND |
| C6 | INT | Output | Interrupt output pin | Open |
| C7 | PD2 | Input | Photo diode connection pin | Connect to GND |
| C8 | PD1 | Output | Photo diode connection pin | Open |
| D1 | SW5 | Output | Control switch pin for matrix driver Connected to E column of matrix LED. | Open |
| D2 | SW6 | Output | Control switch pin for matrix driver Connected to F column of matrix LED. | Open |
| D3 | AGND | Ground | GND for analog block | Connect to GND |
| D4 | NRESET | Input | Reset input pin | (Required pin) |
| D5 | SCL | Input | SPI / I ² C interface common clock input pin | (Required pin) |

PIN FUNCTIONS (continued)

| Pin No. | Pin name | Type | Description | Pin processing at unused |
|---------|----------|----------------|--|--------------------------|
| D6 | SDA | Input / Output | Data input / output pin for I ² C interface At SERSEL pin = High (SPI mode) : Data input pin | (Required pin) |
| D7 | VDD | Power supply | Power supply for I ² C interface | (Required pin) |
| D8 | PD3 | Input | Detection resistor connection pin for photo diode adjustment | Open |
| E1 | SW7 | Output | Control switch pin for matrix driver Connected to G column of matrix LED. | Open |
| E2 | LEDGND3 | Ground | GND for matrix LED | Connect to GND |
| E3 | LEDGND2 | | | |
| E4 | SLAVE | Input / Output | Slave address selection pin for I ² C interface At SERSEL pin = High (SPI mode) : SDO pin | (Required pin) |
| E5 | SERSEL | Input | I ² C / SPI interface selection pin | Connect to GND or VDD |
| E6 | LEDGND1 | Ground | GND for BL pin | Connect to GND |
| E7 | LED1 | Output | Constant current output pin for LED driver | Open |
| F1 | LED16 | Output | Constant current circuit, PWM control output pin Connected to the 6th row of matrix LED. And GPO (open drain) output pin | Open |
| F2 | LED14 | Output | Constant current circuit, PWM control output pin Connected to the 4th row of matrix LED. | Open |
| F3 | LED12 | Output | Constant current circuit, PWM control output pin Connected to the 2nd row of matrix LED. | Open |
| F4 | LED10 | Output | Constant current output pin for LED driver, and GPO (open drain) output pin | Open |
| F5 | LED8 | Output | Constant current output pin for LED driver, and GPO (open drain) output pin | Open |
| F6 | LED6 | Output | Constant current output pin for LED driver | Open |
| F7 | LED4 | Output | Constant current output pin for LED driver | Open |
| F8 | LED2 | Output | Constant current output pin for LED driver | Open |
| G1 | LED17 | Output | Constant current circuit, PWM control output pin Connected to the 7th row of matrix LED. And GPO (open drain) output pin | Open |
| G2 | LED15 | Output | Constant current circuit, PWM control output pin Connected to the 5th row of matrix LED. And GPO (open drain) output pin | Open |
| G3 | LED13 | Output | Constant current circuit, PWM control output pin Connected to the 3rd row of matrix LED. | Open |
| G4 | LED11 | Output | Constant current circuit, PWM control output pin Connected to the 1st row of matrix LED. | Open |
| G5 | LED9 | Output | Constant current output pin for LED driver, and GPO (open drain) output pin | Open |
| G6 | LED7 | Output | Constant current output pin for LED driver | Open |
| G7 | LED5 | Output | Constant current output pin for LED driver | Open |
| G8 | LED3 | Output | Constant current output pin for LED driver | Open |

FUNCTIONAL BLOCK DIAGRAM



Note) This block diagram is for explaining functions. Part of the block diagram may be omitted, or it may be simplified.

OPERATION

1. Power-on / Power-off sequence

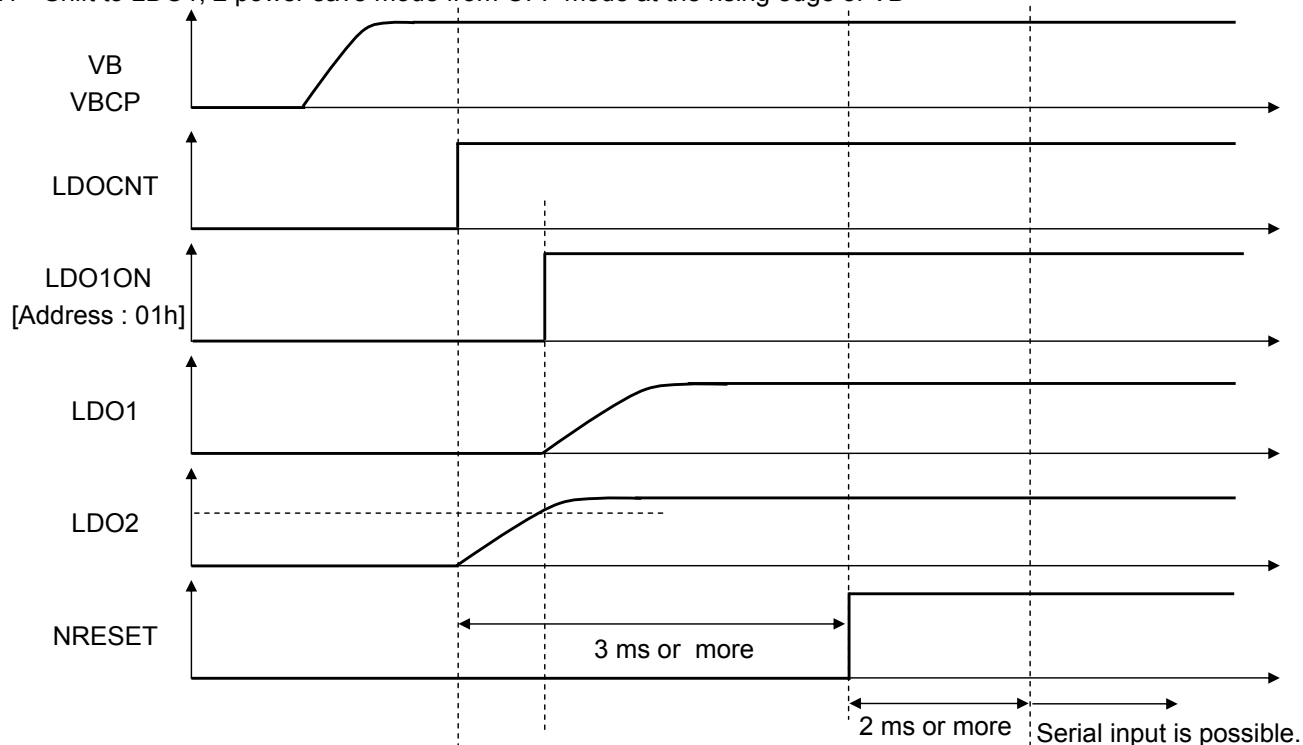
Description of each mode

| Mode | LDOCNT | LDO1ON | LDO2STB | LDO1PS | LDO2PS | Notes |
|--|------------------|--------|---------|---------------|---------------|--|
| OFF | Low | 0 | 0 | 0 | 0 | <ul style="list-style-type: none"> The serial signal is not received at LDOCNT = Low. It is necessary to set LDOCNT to High for the return from OFF mode. |
| OFF ↓ Power save | Low ↓ High | 1 | 0 | 1 | 1 | <ul style="list-style-type: none"> The serial signal can be received after 5 ms from LDOCNT = High. The setting of registers is initialized after this LSI return from OFF mode. Then LDO1 and LDO2 operate in power save mode respectively. |
| Normal | High | 0/1 | 0 | 0 | 0 | <ul style="list-style-type: none"> When NRESET is set to Low, the setting of registers is initialized. Then LDO1 and LDO2 operate in power save mode respectively. The serial signal is turned LDO1 on or off. LDO2 turns on at LDOCNT = High. The serial signal is not received at NRESET = Low. Low period of one or more internal clocks is required during NRESET = Low. NRESET prohibits the input signal of those other than a rectangle wave. When NRESET is set to Low, all the registers are set to the default value. |
| Normal / power save ↓ OFF | High ↓ Low | 0 | 0 | 0/1 ↓ 0 | 0/1 ↓ 0 | <ul style="list-style-type: none"> The setting order to change into OFF mode is as follows. LDOCNT = Low → NRESET = Low, or NRESET = Low → LDOCNT = Low |
| Normal ↓ Power save Power save ↓ Normal | High | 0/1 | 0 | 0/1 | 0/1 | <ul style="list-style-type: none"> LDO1, 2 can be individually shifted to power save mode by the serial signal. It is possible to return from power save mode to normal mode with serial signal. |
| Normal / power save ↓ OFF(LDO1 only) | High ↓ Low | 1 | 1 | 0/1 | 0/1 | <ul style="list-style-type: none"> When LDO1 output is used as power supply for I²C I/F and LDO1 is turned OFF by LDO1ON via serial interface, LDO1 cannot return to ON mode via serial interface. When LDO1 output is used as power supply for I²C I/F, write [1] in LDO2STB first. After that, LDOCNT changes from High to Low, and LDO1 only shifts to OFF mode. |
| OFF(LDO1 only) ↓ Normal / power save | Low ↓ High | | | | | <ul style="list-style-type: none"> If LDOCNT is set to High from Low, this LSI can shift from standby to normal mode. |

OPERATION (continued)

1. Power-on / Power-off sequence (continued)

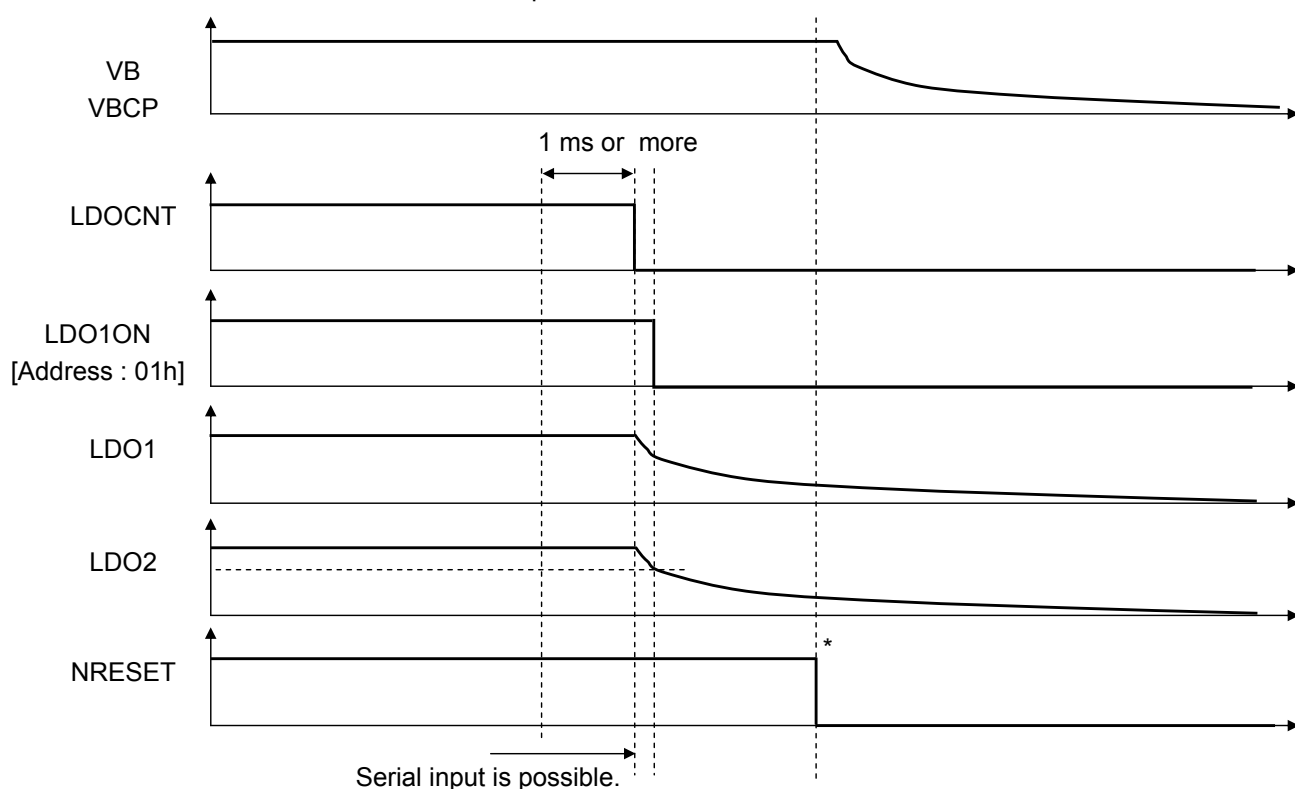
1.1 Shift to LDO1, 2 power save mode from OFF mode at the rising edge of VB



Note) Set LDOCNT to High-level after VB, VBCP reach 3.1 V or more.

LDO1, LDO2 operate at power save mode after they just rise.

1.2 Shift to OFF mode from LDO1, 2 normal / power save mode

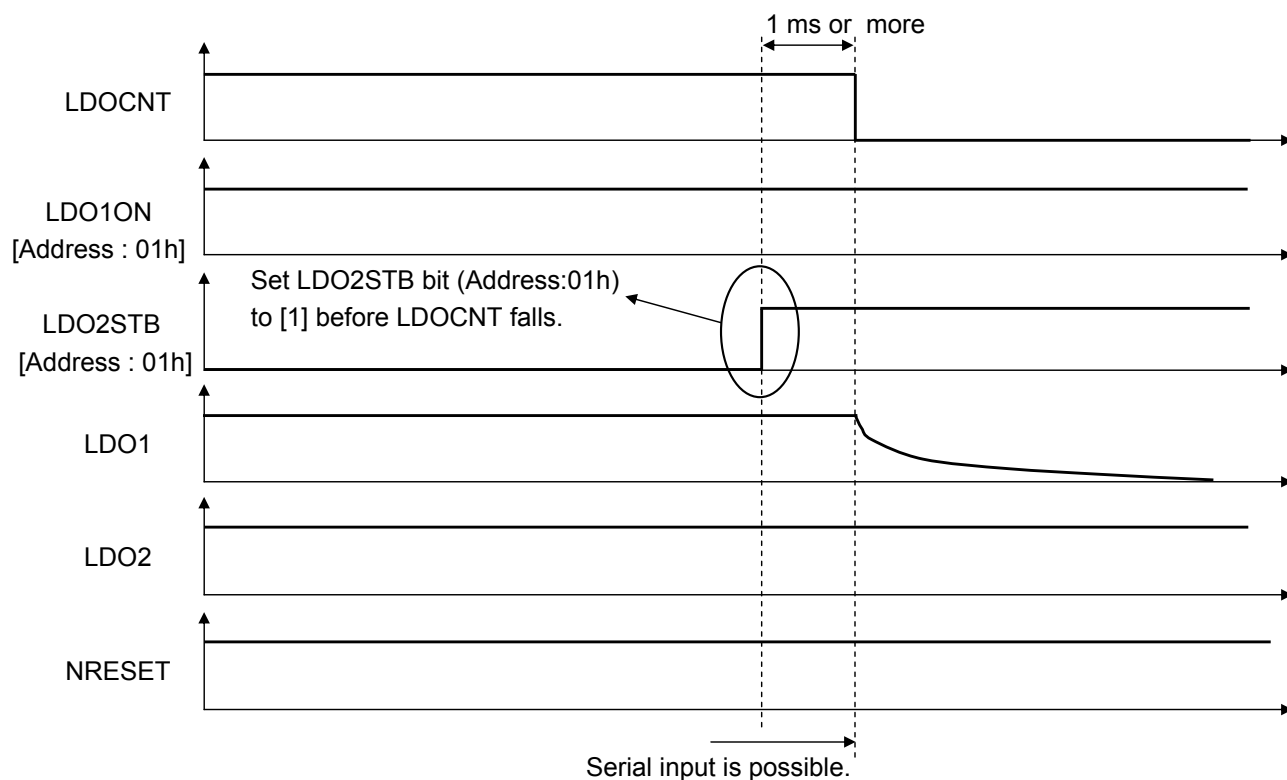


Note) *: There is no problem if NRESET falling timing is before or after LDOCNT falls.

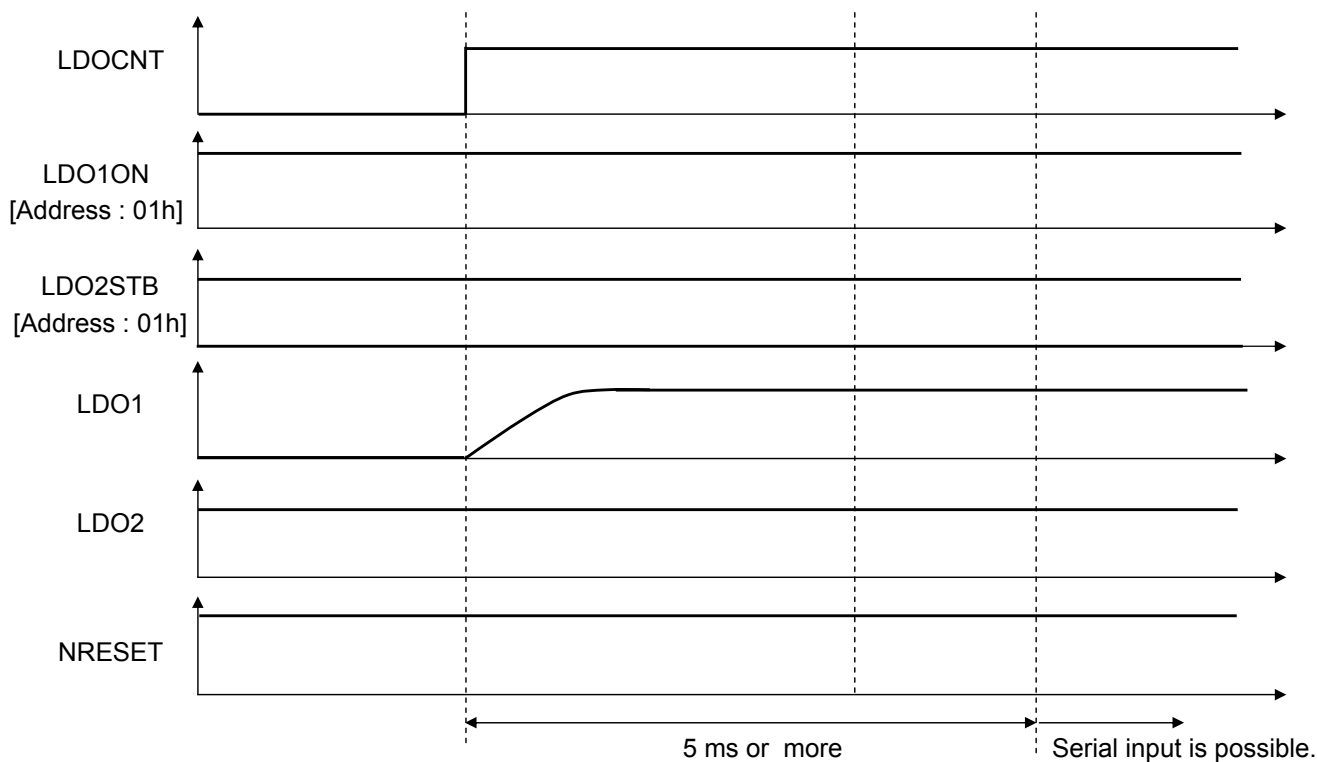
OPERATION (continued)

1. Power-on / Power-off sequence (continued)

1.3 Shift to LDO OFF mode with LDOCNT from normal mode



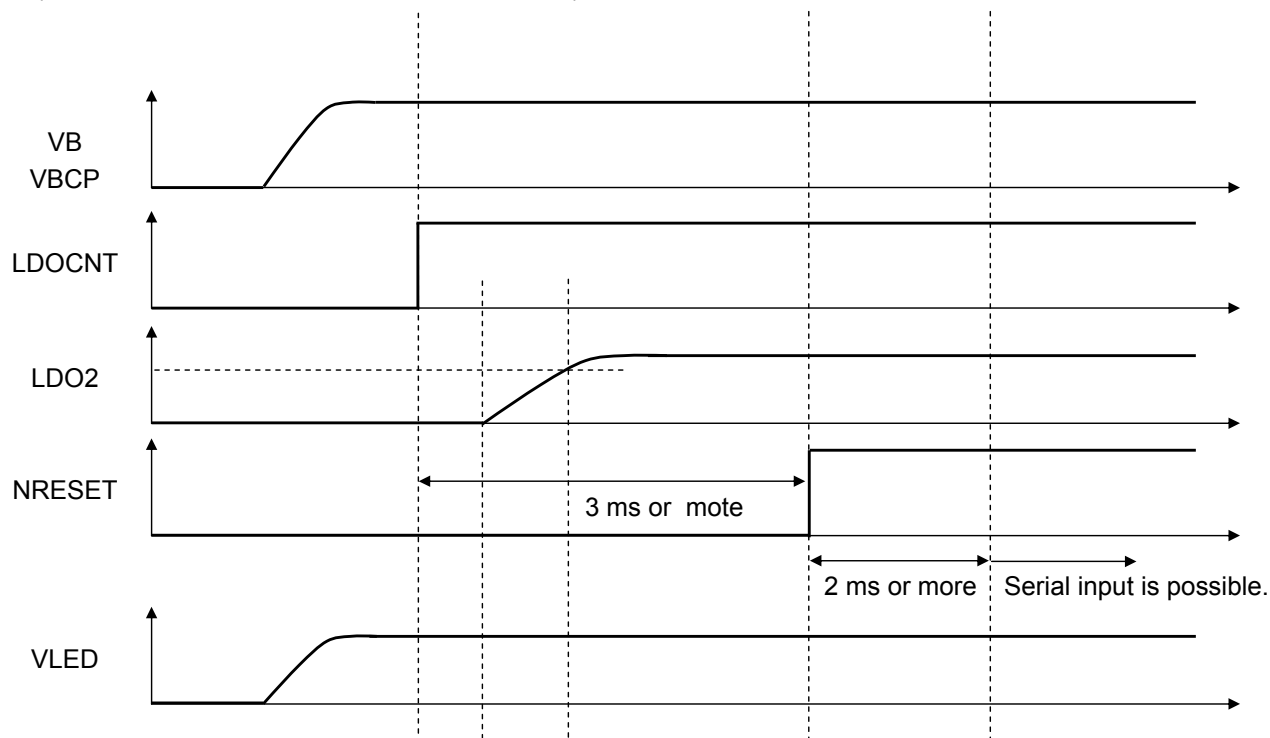
1.4 Shift to normal mode from LDO OFF mode with LDOCNT



OPERATION (continued)

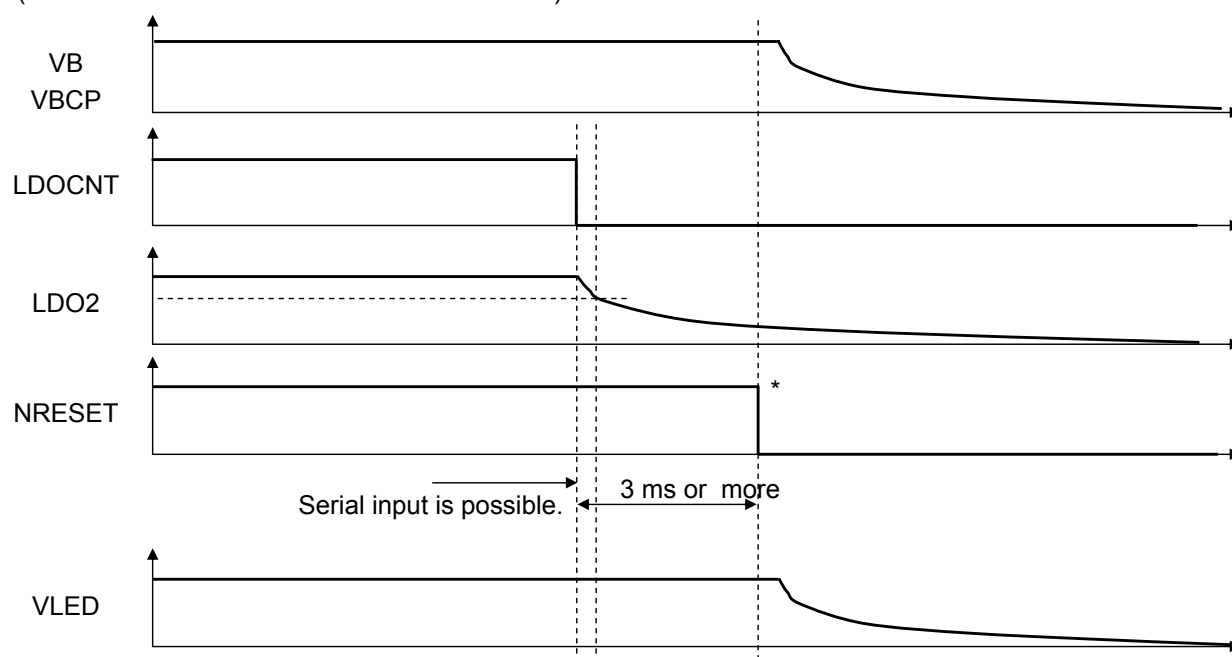
1. Power-on / Power-off sequence (continued)

- 1.5 Power-on sequence when an external power supply is used as LED power supply (VLED)
(at non-connected between CPOUT and VLED)



Note) Rise VLED at the same time as VB,VBCP rise or after VB, VBCP rise.

- 1.6 Power-off sequence when an external power supply is used as LED power supply (VLED)
(at non-connected between CPOUT and VLED)



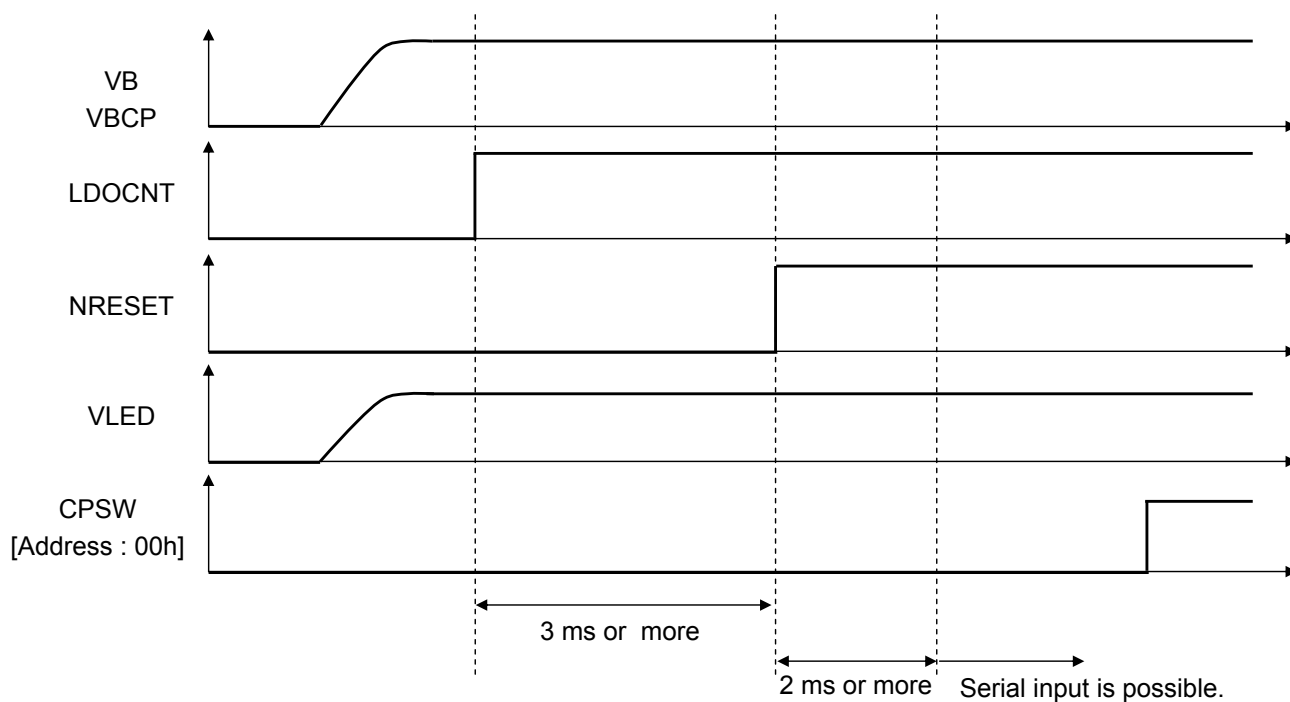
Note) Fall VLED at the same time as VB falls or before VB falls.

* : There is no problem if NRESET falling timing is before or after LDOCNT falls.

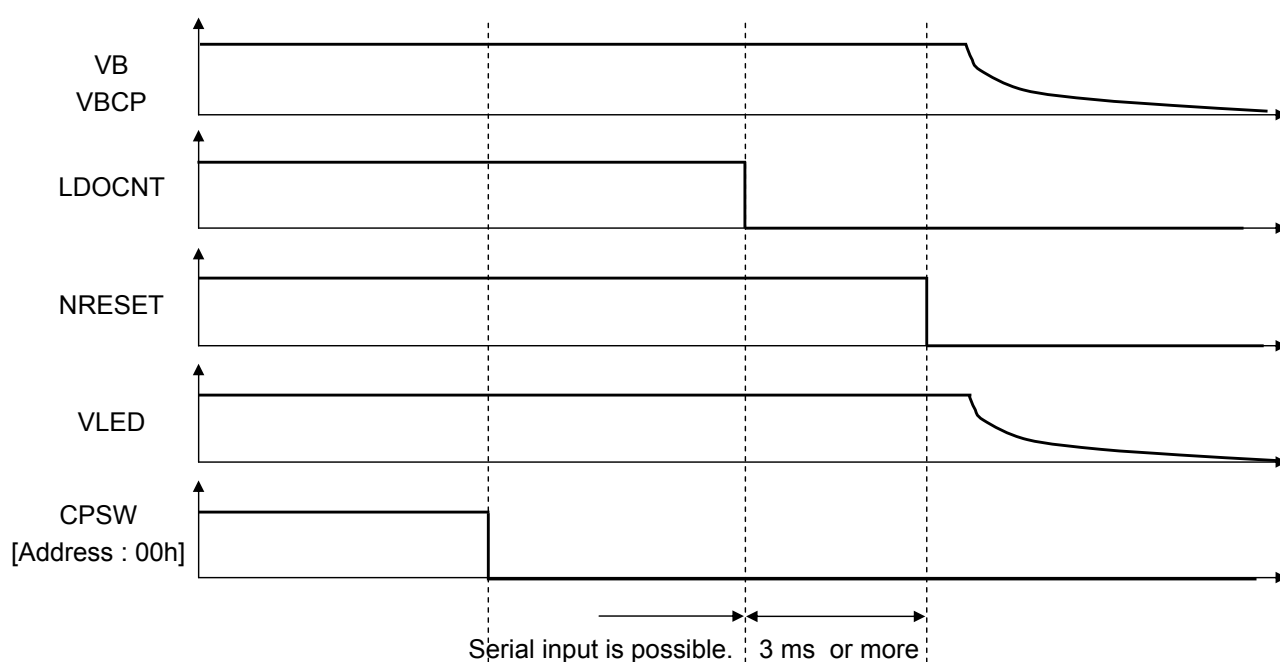
OPERATION (continued)

1. Power-on / Power-off sequence (continued)

1.7 Power-on sequence of charge pump setting



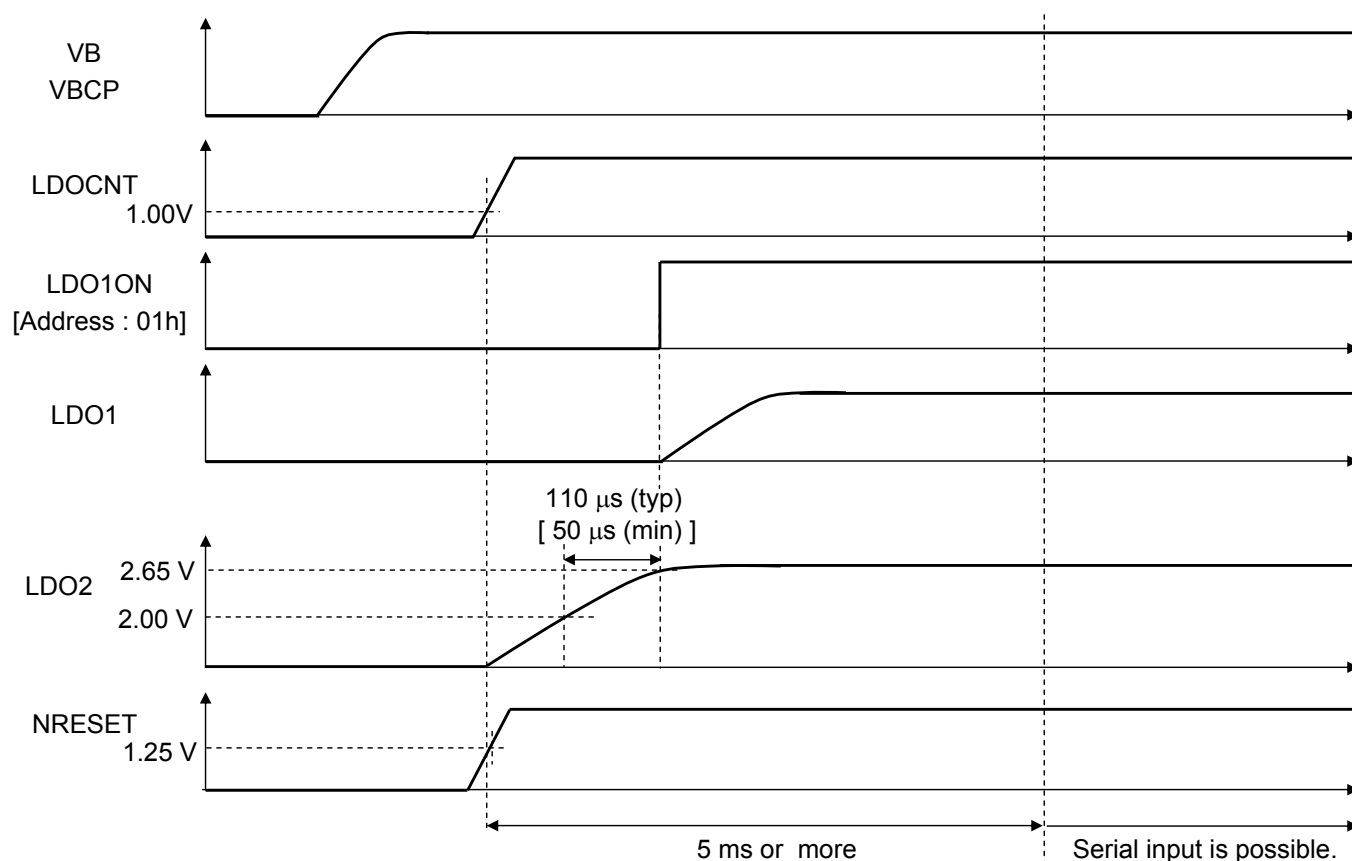
1.8 Power-off sequence of charge pump setting



OPERATION (continued)

1. Power-on / Power-off sequence (continued)

1.9 Start-up sequence when terminal NRESET is not used



Note) When the period of time that LDO2 pin voltage rises from 2.0 V to 2.65 V is 50 ms or more, this LSI operates normally even if LDOCNT pin and NRESET pin are connected together.

Supplement) Electrical characteristics of LDO2 pin rising time : 110 μs (typ), 50 μs (min)

OPERATION (continued)

1. Power-on / Power-off sequence (continued)

1.10 Mode of VBAT / LDOCNT

| VBAT | LDOCNT | LDO2STB (Address : 01h) | LDO1ON (Address : 01h) | LDO1PS (Address : 01h) | LDO2PS (Address : 01h) | MODE (LDO1) | MODE (LDO2) |
|------|--------|----------------------------|---------------------------|---------------------------|---------------------------|----------------|----------------|
| Low | Low | "0" | "0" | "0" | "0" | OFF | OFF |
| Low | High | "0" | "0" | "0" | "0" | Prohibited | |
| High | Low | "0" | "0" | "0" | "0" | OFF | OFF |
| High | High | "X" | "0" | "X" | "0" | OFF | ON |
| High | High | "X" | "0" | "X" | "1" | OFF | Power save |
| High | High | "X" | "1" | "0" | "0" | ON | ON |
| High | High | "X" | "1" | "0" | "1" | ON | Power save |
| High | High | "X" | "1" | "1" | "0" | Power save | ON |
| High | High | "X" | "1" | "1" | "1" | Power save | Power save |
| High | Low | "1" | "X" | "X" | "0" | OFF | ON |
| High | Low | "1" | "X" | "X" | "1" | OFF | Power save |

Note) As for VBAT and LDOCNT,
Low : 0 V, High : 3.1 V to 4.6 V (operating supply voltage range)

1.11 Power-on sequence of VDD

It is possible to turn on/off VDD at any timing regardless of ON/OFF of other power supplies.
But when SLAVE is connected to VDD level outside the LSI, it is impossible to turn on VDD with VB falling.

OPERATION (continued)

2. Register map

2.1 Address 00h to 1Fh

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|-----------|-----------|--------|------------|-------------|-------------|------------|------------|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 00h | R/W | POWERCNT | 00h | — | — | — | CPRET MODE | CP CLKSEL20 | CP CLKSEL15 | OSCEN | CPSW |
| 01h | R/W | LDOCNT | 0Eh | — | — | — | LDO2 STB | LDO1PS | LDO2PS | LDO1ON | LDO1 VSEL |
| 02h | R | STATE CHANGE | 01h | — | — | — | CPERR | CP20 | CP15 | VB | CPOFF |
| 03h | R/W | STATE FORCE | 00h | RETURN VB | ERRMSK | ERRCLR | ERR STOP | FCP20 | FCP15 | FVB | FCPOFF |
| 04h *1 | — | — | — | — | — | — | — | — | — | — | — |
| 05h | R/W | CLKSEL | 00h | — | — | — | — | — | — | CLKOUT | EXTCLK SEL |
| 06h | R/W | GPOEN | 00h | — | — | GPO6EN | GPO5EN | GPO4EN | GPO3EN | GPO2EN | GPO1EN |
| 07h | R/W | OOUT | 00h | — | — | OOUT6 | OOUT5 | OOUT4 | OOUT3 | OOUT2 | OOUT1 |
| 08h | R/W | IOSEL | 00h | — | — | — | — | — | IOSEL3 | IOSEL2 | IOSEL1 |
| 09h | R/W | IOOUT | 00h | — | — | — | — | — | IOOUT3 | IOOUT2 | IOOUT1 |
| 0Ah | R/W | VOUTSEL | 00h | — | — | — | — | — | IOVSEL3 | IOVSEL2 | IOVSEL1 |
| 0Bh | R | INT1 | 00h | SDET | VBDET | IOSTA3 | IOSTA2 | IOSTA1 | IOFAC3 | IOFAC2 | IOFAC1 |
| 0Ch | W | INTCLR1 | 00h | — | VBDET CLR | — | — | — | IOFAC3 CLR | IOFAC2 CLR | IOFAC1 CLR |
| 0Dh | R/W | INTMSK1 | 00h | SDET MSK | VBDET MSK | — | — | — | IOFAC3 MSK | IOFAC2 MSK | IOFAC1 MSK |
| 0Eh | R/W | IOPLD | 00h | — | — | — | — | — | IOPLD3 | IOPLD2 | IOPLD1 |
| 0Fh | R/W | IODET | 00h | — | — | — | — | — | IODET3 | IODET2 | IODET1 |

Note) Read value of " — "(the blanks) is [0] in the register map.

*1: Address 04h is register for the LSI test. Use them with the default value [0].

OPERATION (continued)

2. Register map (continued)

2.1 Address 00h to 1Fh (continued)

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|---------------|-------------|---------------|-------------|---------------|-------------|----------------|------------|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 10h | R/W | LED CNT1 | 00h | LEDCNT1EN | LED1ACT | LED1GRP1 | LED1GRP2 | LEDCNT1LED10 | LEDCNT1LED9 | LEDCNT1LED8 | LED1MTX |
| 11h | R/W | LED CNT2 | 00h | LEDCNT2EN | LED2ACT | LED2GRP1 | LED2GRP2 | LEDCNT2LED10 | LEDCNT2LED9 | LEDCNT2LED8 | LED2MTX |
| 12h | R/W | VDETLED CNT1 | 00h | VDETLED8EN | VDETLED7EN | VDETLED6EN | VDETLED5EN | VDETLED4EN | VDETLED3EN | VDETLED2EN | VDETLED1EN |
| 13h | R/W | VDETLED CNT2 | 00h | — | — | — | — | — | — | VDETLED10EN | VDETLED9EN |
| 14h | R/W | VDETLED CNT3 | 00h | VDETLED17EN | VDETLED16EN | VDETLED15EN | VDETLED14EN | VDETLED13EN | VDETLED12EN | VDETLED11EN | VDETMTX |
| 15h | R | INT2 | 00h | — | INTLEDG1 | INTLUT | ADCINT | LICGAININT | LICDRV2INT | FRMINT | SLPMAT |
| 16h | W | INTCLR2 | 00h | — | INTLEDG1CLR | INTLUTCLR | ADCINTCLR | LICGAININTCLR | LICDRV2CLR | FRMINTCLR | SLPMATCLR |
| 17h | R/W | INTMSK2 | 00h | — | INTLEDG1MSK | INTLUTMSK | ADCINTMSK | LICGAINMSK | LICDRV2MSK | FRMINTMSK | SLPMATMSK |
| 18h | R | ADCRD1 | 00h | ADCGD(NPOWD) | GAINST | LIC_DATA[3:0] | | | | ADC_DATA[1:0] | |
| 19h | R | ADCRD2 | 00h | ADC_DATA[9:2] | | | | | | | |
| 1Ah | R/W | GAINTH | 08h | — | — | — | RSTGAIN | GAINTH[3:0] | | | |
| 1Bh | R/W | GSWTHH | FAh | GSWTHH[7:0] | | | | | | | |
| 1Ch | R/W | GSWTHL | 07h | GSWTHL[7:0] | | | | | | | |
| 1Dh | R/W | INTSEL | 00h | — | RSTCNT | INTSEL[5:0] | | | | | |
| 1Eh | R/W | LICADWAIT | 0Ch | — | — | — | ADWAIT[4:0] | | | | |
| 1Fh | R/W | REGSEL | 00h | — | — | — | — | — | — | REGSEL[1:0] *2 | |

Note) Read value of " — "(the blanks) is [0] in the register map.

*2 : It is possible to change the register map of Address 20h to 6Fh by setting REGSEL[1: 0]. There are four choices in it.

REGSEL[1:0] = [00] CPU can access the register related to from LED1 to LED10.

REGSEL[1:0] = [01] CPU can access the register related to the modulated LED light.

REGSEL[1:0] = [10] CPU can access RAM1 and the register related to the matrix LED.

REGSEL[1:0] = [11] CPU can access RAM2 and the register related to the matrix LED.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh

1) At REGSEL[1:0] = [00]

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|-----------------|----|-----------------|----|----------------|----------|-----------|---------|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 20h | R/W | GROUP ASSIGN1 | 55h | LED4[1:0] | | LED3[1:0] | | LED2[1:0] | | LED1[1:0] | |
| 21h | R/W | GROUP ASSIGN2 | 28h | — | — | LED7[1:0] | | LED6[1:0] | | LED5[1:0] | |
| 22h | R/W | GRP1CNT | 00h | GRP1LEDSET[7:0] | | | | | | | |
| 23h | R/W | GRP2CNT | 00h | GRP2LEDSET[7:0] | | | | | | | |
| 24h | R/W | LEDDRV2 CNT | 00h | — | — | — | — | — | LED10ON | LED9ON | LED8ON |
| 25h | R/W | CNT8 | 28h | ILED8SET[7:0] | | | | | | | |
| 26h | R/W | CNT9 | 28h | ILED9SET[7:0] | | | | | | | |
| 27h | R/W | CNT10 | 28h | ILED10SET[7:0] | | | | | | | |
| 28h | R/W | GRP1PWM CNT | 00h | GRP1PWMEN | | GRP1PWMSET[6:0] | | | | | |
| 29h | R/W | PWM8 CNT | 00h | PWM8EN | | PWM8SET[6:0] | | | | | |
| 2Ah | R/W | PWM9 CNT | 00h | PWM9EN | | PWM9SET[6:0] | | | | | |
| 2Bh | R/W | PWM10 CNT | 00h | PWM10EN | | PWM10SET[6:0] | | | | | |
| 2Ch | R/W | HOTARU CNT | 88h | HOTATT2[3:0] | | | | HOTATT1[3:0] | | | |
| 2Dh | R/W | HOTARU ASSIGN | 00h | — | — | — | — | — | HOTA10EN | HOTA9EN | HOTA8EN |
| 2Eh | — | — | — | — | — | — | — | — | — | — | — |
| 2Fh | R/W | SLOPE GRP1 | 00h | SLPGRP1R[3:0] | | | | SLPGRP1F[3:0] | | | |
| 30h | R/W | SLOPE LED8 | 00h | SLPLED8R[3:0] | | | | SLPLED8F[3:0] | | | |
| 31h | R/W | SLOPE LED9 | 00h | SLPLED9R[3:0] | | | | SLPLED9F[3:0] | | | |
| 32h | R/W | SLOPE LED10 | 00h | SLPLED10R[3:0] | | | | SLPLED10F[3:0] | | | |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh (continued)

1) At REGSEL[1:0] = [00] (continued)

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|----------------|--------------|--------------|--------------|----------------|--------------|--------------|--------------|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 33h | R/W | HOTARU8CNT1 | F8h | DUTYMAX8[3:0] | | | | DUTYMID8[3:0] | | | |
| 34h | R/W | HOTARU8CNT2 | 00h | — | — | — | — | DUTYMIN8[3:0] | | | |
| 35h | R/W | HOTARU8CNT3 | 88h | HOTA8DT2[3:0] | | | | HOTA8DT1[3:0] | | | |
| 36h | R/W | HOTARU8CNT4 | 88h | HOTA8DT4[3:0] | | | | HOTA8DT3[3:0] | | | |
| 37h | R/W | HOTARU9CNT1 | F8h | DUTYMAX9[3:0] | | | | DUTYMID9[3:0] | | | |
| 38h | R/W | HOTARU9CNT2 | 00h | — | — | — | — | DUTYMIN9[3:0] | | | |
| 39h | R/W | HOTARU9CNT3 | 88h | HOTA9DT2[3:0] | | | | HOTA9DT1[3:0] | | | |
| 3Ah | R/W | HOTARU9CNT4 | 88h | HOTA9DT4[3:0] | | | | HOTA9DT3[3:0] | | | |
| 3Bh | R/W | HOTARU10CNT1 | F8h | DUTYMAX10[3:0] | | | | DUTYMID10[3:0] | | | |
| 3Ch | R/W | HOTARU10CNT2 | 00h | — | — | — | — | DUTYMIN10[3:0] | | | |
| 3Dh | R/W | HOTARU10CNT3 | 88h | HOTA10DT2[3:0] | | | | HOTA10DT1[3:0] | | | |
| 3Eh | R/W | HOTARU10CNT4 | 88h | HOTA10DT4[3:0] | | | | HOTA10DT3[3:0] | | | |
| 45h | R/W | STROBE1 | AAh | STBLED 17 | STBLED 16 | STBLED 15 | STBLED 14 | STBLED 13 | STBLED 12 | STBLED 11 | STBLED 10 |
| 46h | R/W | STROBE2 | 02h | — | — | — | — | — | STBEN | STBLED 8 | STBLED 9 |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh (continued)

2) At REGSEL[1:0] = [01]

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|---------------|------------|----------|--------------|---------------|----------|-------|----|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 20h | R/W | LICEN | 28h | — | GAINCNT | ADCAVERA | LICTIME[2:0] | | ADCSTART | LICEN | |
| 21h | R/W | LICTIME | B4h | GCHGMOD | HYSMODESEL | LICHYSGL | LICHYSGH | LICTH0D[3:0] | | | |
| 22h | R/W | LICSLP | 44h | SLPRATEF[3:0] | | | | SLPRATER[3:0] | | | |
| 23h | R/W | LICTH0 | 0Ah | LICTH0[7:0] | | | | | | | |
| 24h | R/W | LICTH1 | 2Ah | LICTH1[7:0] | | | | | | | |
| 25h | R/W | LICTH2 | 4Ah | LICTH2[7:0] | | | | | | | |
| 26h | R/W | LICTH3 | 6Ah | LICTH3[7:0] | | | | | | | |
| 27h | R/W | LICTH4 | 8Ah | LICTH4[7:0] | | | | | | | |
| 28h | R/W | LICTH5 | AAh | LICTH5[7:0] | | | | | | | |
| 29h | R/W | LICTH6 | CAh | LICTH6[7:0] | | | | | | | |
| 2Ah | R/W | LICTH7 | FAh | LICTH7[7:0] | | | | | | | |
| 2Bh | R/W | LICTH8 | 10h | LICTH8[7:0] | | | | | | | |
| 2Ch | R/W | LICTH9 | 30h | LICTH9[7:0] | | | | | | | |
| 2Dh | R/W | LICTH10 | 60h | LICTH10[7:0] | | | | | | | |
| 2Eh | R/W | LICTH11 | 90h | LICTH11[7:0] | | | | | | | |
| 2Fh | R/W | LICTH12 | B0h | LICTH12[7:0] | | | | | | | |
| 30h | R/W | LICTH13 | D0h | LICTH13[7:0] | | | | | | | |
| 31h | R/W | LICTH14 | F0h | LICTH14[7:0] | | | | | | | |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh (continued)

2) At REGSEL[1:0] = [01] (continued)

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|---------------|----|-----------|-------------|----------------|----------------|----------------|----------------|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 32h | R/W | LICLUT0 | 08h | LICLUT0[7:0] | | | | | | | |
| 33h | R/W | LICLUT1 | 10h | LICLUT1[7:0] | | | | | | | |
| 34h | R/W | LICLUT2 | 18h | LICLUT2[7:0] | | | | | | | |
| 35h | R/W | LICLUT3 | 20h | LICLUT3[7:0] | | | | | | | |
| 36h | R/W | LICLUT4 | 28h | LICLUT4[7:0] | | | | | | | |
| 37h | R/W | LICLUT5 | 30h | LICLUT5[7:0] | | | | | | | |
| 38h | R/W | LICLUT6 | 38h | LICLUT6[7:0] | | | | | | | |
| 39h | R/W | LICLUT7 | 40h | LICLUT7[7:0] | | | | | | | |
| 3Ah | R/W | LICLUT8 | 48h | LICLUT8[7:0] | | | | | | | |
| 3Bh | R/W | LICLUT9 | 50h | LICLUT9[7:0] | | | | | | | |
| 3Ch | R/W | LICLUT10 | 60h | LICLUT10[7:0] | | | | | | | |
| 3Dh | R/W | LICLUT11 | 70h | LICLUT11[7:0] | | | | | | | |
| 3Eh | R/W | LICLUT12 | 80h | LICLUT12[7:0] | | | | | | | |
| 3Fh | R/W | LICLUT13 | 90h | LICLUT13[7:0] | | | | | | | |
| 40h | R/W | LICLUT14 | A0h | LICLUT14[7:0] | | | | | | | |
| 41h | R/W | LICLUT15 | B0h | LICLUT15[7:0] | | | | | | | |
| 42h | R/W | LICAPPED | 01h | — | — | — | LICLED10 | LICLED9 | LICLED8 | LICGRP2 | LICGRP1 |
| 43h | R/W | LIC INVERT | 1Ch | — | — | — | LICINVLED10 | LICINV LED9 | LICINV LED8 | LICINV GRP2 | LICINV GRP1 |
| 44h | R/W | LIC LEDSET | 32h | — | — | LICDEFGP2 | LICDEFGP1 | LICD2TH[3:0] | | | |
| 45h | R/W | ADAJH | 00h | ADAJH[7:0] | | | | | | | |
| 46h | R/W | ADAJL | 00h | ADAJL[7:0] | | | | | | | |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh (continued)

3) At REGSEL[1:0] = [10] or [11]

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|------|--------------|--------------|----------------|---------------|--------------|--------------|--------------|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 20h | R/W | MTXON | 00h | — | — | — | MTXON DETTM | MTXON CPMD | MTXTIME[1:0] | | MTXON |
| 21h | R/W | MTXDATA | 00h | — | — | — | — | — | — | MTXDATA[1:0] | |
| 22h | R/W | RAMRST | 00h | — | — | — | — | — | — | RAM1 | RAM2 |
| 23h | R/W | SCROLL | 00h | — | — | — | — | — | — | — | SCLON |
| 24h | R/W | SCLTIME | 00h | — | — | — | — | — | — | SCLTIME[1:0] | |
| 25h | R/W | XCONST | 00h | — | X11 CONST | X12 CONST | X13 CONST | X14 CONST | X15 CONST | X16 CONST | X17 CONST |
| 26h | R/W | YCONST | 00h | — | SW1 CONST | SW2 CONST | SW3 CONST | SW4 CONST | SW5 CONST | SW6 CONST | SW7 CONST |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh (continued)

3) At REGSEL[1:0] = [10] or [11] (continued)

Address 3Fh to 6Fh access RAM1 at REGSEL[1:0] = [10].

Address 3Fh to 6Fh access RAM2 at REGSEL[1:0] = [11].

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|-----------|----|----|----|-----------|----|-----------|----|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 3Fh | R/W | A1 | 00h | BLA1[3:0] | | | | FRA1[1:0] | | DLA1[1:0] | |
| 40h | R/W | A2 | 00h | BLA2[3:0] | | | | FRA2[1:0] | | DLA2[1:0] | |
| 41h | R/W | A3 | 00h | BLA3[3:0] | | | | FRA3[1:0] | | DLA3[1:0] | |
| 42h | R/W | A4 | 00h | BLA4[3:0] | | | | FRA4[1:0] | | DLA4[1:0] | |
| 43h | R/W | A5 | 00h | BLA5[3:0] | | | | FRA5[1:0] | | DLA5[1:0] | |
| 44h | R/W | A6 | 00h | BLA6[3:0] | | | | FRA6[1:0] | | DLA6[1:0] | |
| 45h | R/W | A7 | 00h | BLA7[3:0] | | | | FRA7[1:0] | | DLA7[1:0] | |
| 46h | R/W | B1 | 00h | BLB1[3:0] | | | | FRB1[1:0] | | DLB1[1:0] | |
| 47h | R/W | B2 | 00h | BLB2[3:0] | | | | FRB2[1:0] | | DLB2[1:0] | |
| 48h | R/W | B3 | 00h | BLB3[3:0] | | | | FRB3[1:0] | | DLB3[1:0] | |
| 49h | R/W | B4 | 00h | BLB4[3:0] | | | | FRB4[1:0] | | DLB4[1:0] | |
| 4Ah | R/W | B5 | 00h | BLB5[3:0] | | | | FRB5[1:0] | | DLB5[1:0] | |
| 4Bh | R/W | B6 | 00h | BLB6[3:0] | | | | FRB6[1:0] | | DLB6[1:0] | |
| 4Ch | R/W | B7 | 00h | BLB7[3:0] | | | | FRB7[1:0] | | DLB7[1:0] | |
| 4Dh | R/W | C1 | 00h | BLC1[3:0] | | | | FRC1[1:0] | | DLC1[1:0] | |
| 4Eh | R/W | C2 | 00h | BLC2[3:0] | | | | FRC2[1:0] | | DLC2[1:0] | |
| 4Fh | R/W | C3 | 00h | BLC3[3:0] | | | | FRC3[1:0] | | DLC3[1:0] | |
| 50h | R/W | C4 | 00h | BLC4[3:0] | | | | FRC4[1:0] | | DLC4[1:0] | |
| 51h | R/W | C5 | 00h | BLC5[3:0] | | | | FRC5[1:0] | | DLC5[1:0] | |
| 52h | R/W | C6 | 00h | BLC6[3:0] | | | | FRC6[1:0] | | DLC6[1:0] | |
| 53h | R/W | C7 | 00h | BLC7[3:0] | | | | FRC7[1:0] | | DLC7[1:0] | |
| 54h | R/W | D1 | 00h | BLD1[3:0] | | | | FRD1[1:0] | | DLD1[1:0] | |
| 55h | R/W | D2 | 00h | BLD2[3:0] | | | | FRD2[1:0] | | DLD2[1:0] | |
| 56h | R/W | D3 | 00h | BLD3[3:0] | | | | FRD3[1:0] | | DLD3[1:0] | |
| 57h | R/W | D4 | 00h | BLD4[3:0] | | | | FRD4[1:0] | | DLD4[1:0] | |
| 58h | R/W | D5 | 00h | BLD5[3:0] | | | | FRD5[1:0] | | DLD5[1:0] | |
| 59h | R/W | D6 | 00h | BLD6[3:0] | | | | FRD6[1:0] | | DLD6[1:0] | |
| 5Ah | R/W | D7 | 00h | BLD7[3:0] | | | | FRD7[1:0] | | DLD7[1:0] | |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

2. Register map (continued)

2.2 Address 20h to 6Fh (continued)

3) At REGSEL[1:0] = [10] or [11] (continued)

Address 3Fh to 6Fh access RAM1 at REGSEL[1:0] = [10].

Address 3Fh to 6Fh access RAM2 at REGSEL[1:0] = [11].

| Sub Address | R/W | Register Name | Default | Data | | | | | | | |
|-------------|-----|---------------|---------|-----------|----|----|----|-----------|----|-----------|----|
| | | | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| 5Bh | R/W | E1 | 00h | BLE1[3:0] | | | | FRE1[1:0] | | DLE1[1:0] | |
| 5Ch | R/W | E2 | 00h | BLE2[3:0] | | | | FRE2[1:0] | | DLE2[1:0] | |
| 5Dh | R/W | E3 | 00h | BLE3[3:0] | | | | FRE3[1:0] | | DLE3[1:0] | |
| 5Eh | R/W | E4 | 00h | BLE4[3:0] | | | | FRE4[1:0] | | DLE4[1:0] | |
| 5Fh | R/W | E5 | 00h | BLE5[3:0] | | | | FRE5[1:0] | | DLE5[1:0] | |
| 60h | R/W | E6 | 00h | BLE6[3:0] | | | | FRE6[1:0] | | DLE6[1:0] | |
| 61h | R/W | E7 | 00h | BLE7[3:0] | | | | FRE7[1:0] | | DLE7[1:0] | |
| 62h | R/W | F1 | 00h | BLF1[3:0] | | | | FRF1[1:0] | | DLF1[1:0] | |
| 63h | R/W | F2 | 00h | BLF2[3:0] | | | | FRF2[1:0] | | DLF2[1:0] | |
| 64h | R/W | F3 | 00h | BLF3[3:0] | | | | FRF3[1:0] | | DLF3[1:0] | |
| 65h | R/W | F4 | 00h | BLF4[3:0] | | | | FRF4[1:0] | | DLF4[1:0] | |
| 66h | R/W | F5 | 00h | BLF5[3:0] | | | | FRF5[1:0] | | DLF5[1:0] | |
| 67h | R/W | F6 | 00h | BLF6[3:0] | | | | FRF6[1:0] | | DLF6[1:0] | |
| 68h | R/W | F7 | 00h | BLF7[3:0] | | | | FRF7[1:0] | | DLF7[1:0] | |
| 69h | R/W | G1 | 00h | BLG1[3:0] | | | | FRG1[1:0] | | DLG1[1:0] | |
| 6Ah | R/W | G2 | 00h | BLG2[3:0] | | | | FRG2[1:0] | | DLG2[1:0] | |
| 6Bh | R/W | G3 | 00h | BLG3[3:0] | | | | FRG3[1:0] | | DLG3[1:0] | |
| 6Ch | R/W | G4 | 00h | BLG4[3:0] | | | | FRG4[1:0] | | DLG4[1:0] | |
| 6Dh | R/W | G5 | 00h | BLG5[3:0] | | | | FRG5[1:0] | | DLG5[1:0] | |
| 6Eh | R/W | G6 | 00h | BLG6[3:0] | | | | FRG6[1:0] | | DLG6[1:0] | |
| 6Fh | R/W | G7 | 00h | BLG7[3:0] | | | | FRG7[1:0] | | DLG7[1:0] | |

Note) Read value of " — "(the blanks) is [0] in the register map.

OPERATION (continued)

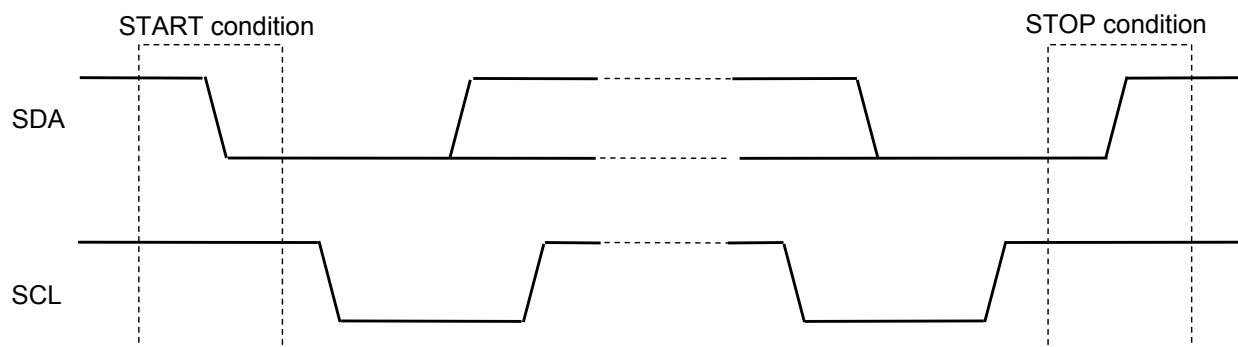
3. I²C-bus interface

3.1 Basic Rules

- This LSI, I²C-bus, is designed to correspond to the Standard-mode (100 kbps) and Fast-mode(400 kbps) devices in the version 2.1 of NXP's specification. However, it does not correspond to the H_S-mode (to 3.4 Mbps).
- This LSI will operate as a slave device in the I²C-bus system. This LSI will not operate as a master device.
- The program operation check of this LSI has not been conducted on the multi-master bus system and the mix-speed bus system, yet. The connected confirmation of this LSI to the CBUS receiver also has not been checked. Please confirm with our company if it will be used in these mode systems.
- The I²C is the brand of NXP.

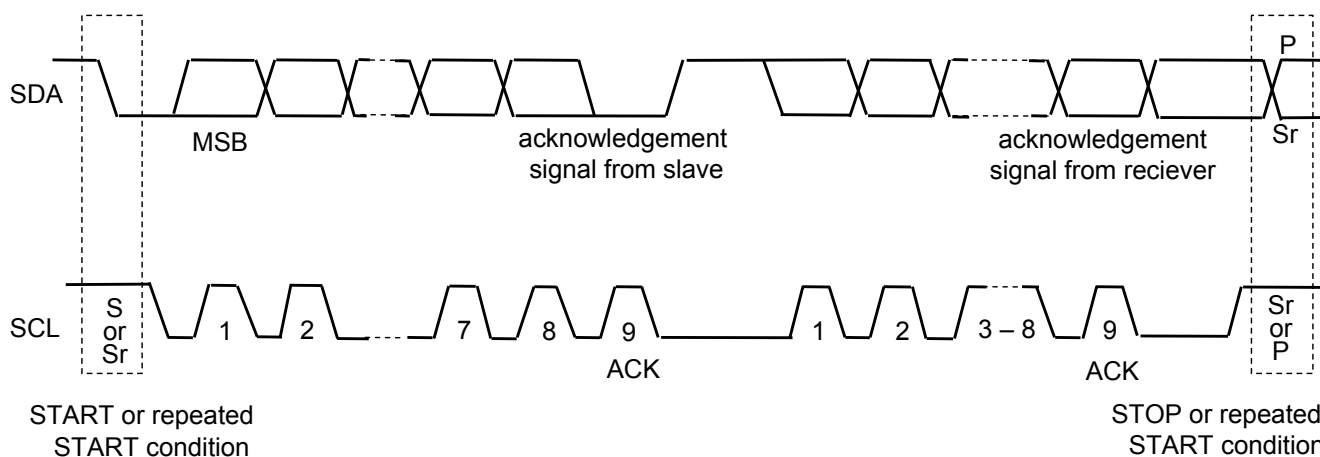
3.2 START and STOP conditions

A High to Low transition on the SDA line while SCL is High is one such unique case. This situation indicates a START condition. A Low to High transition on the SDA line while SCL is High defines a STOP condition. START and STOP conditions are always generated by the master. The bus is considered to be free again a certain time after the STOP condition.



3.3 Transferring Data

Every byte put on the SDA line must be 8-bit long. The number of bytes that can be transmitted per transfer is unrestricted. Each byte has to be followed by an acknowledge bit. Data is transferred with the most significant bit (MSB) first.



OPERATION (continued)

3. I²C-bus interface (continued)

3.4 DATA format

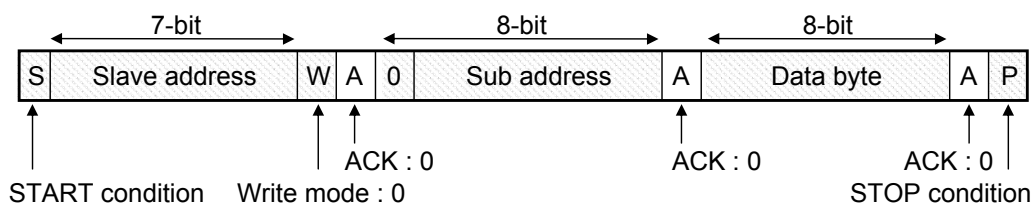
When LSI format is used in this LSI, SERSEL pin should be fixed to Low-level.

Slave address of this LSI is 70h under the condition of SLAVE pin = Low, and is 71h under the condition of SLAVE pin = High.

Write mode

When MSB of sub address (8-bit) is "0", the sub address is not incremented automatically.

By transmitting data bytes continuously, the next data bytes are written into the same sub address. by transmitting data byte continuously

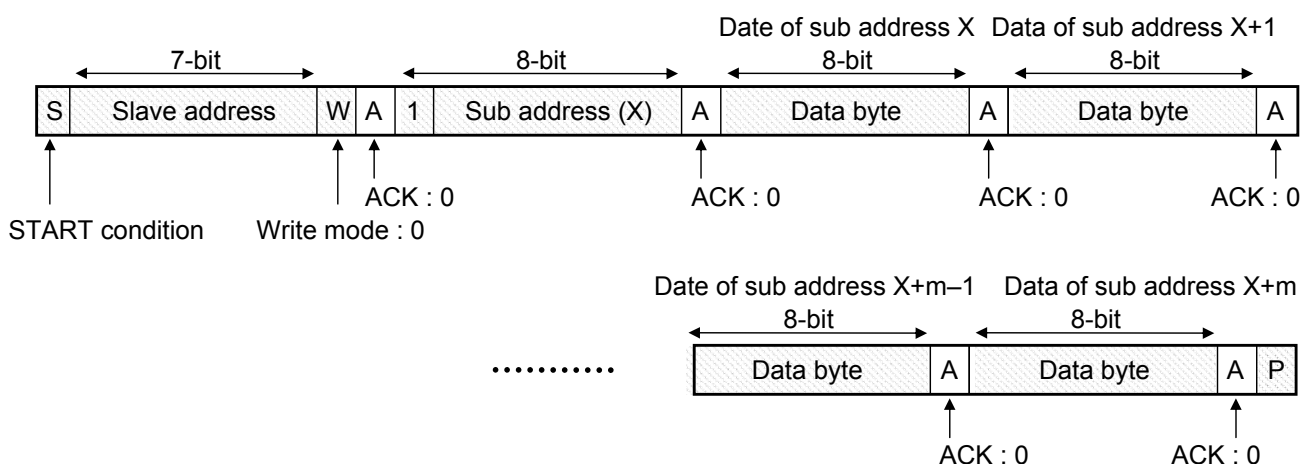




Write mode (Auto increment mode)

When MSB of sub address (8-bit) is "1", auto increment mode is defined.

By transmitting data bytes continuously, the data bytes are written into continuous sub address.

The sub address is incremented automatically.



 : Data transmission from Master
 : Data transmission from Slave

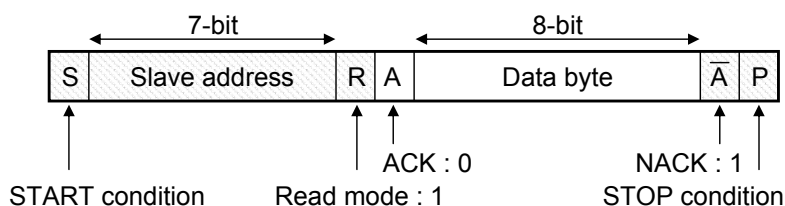
OPERATION (continued)

3. I²C-bus interface (continued)

3.4 DATA format (continued)

Read mode (In case sub address is not specified)

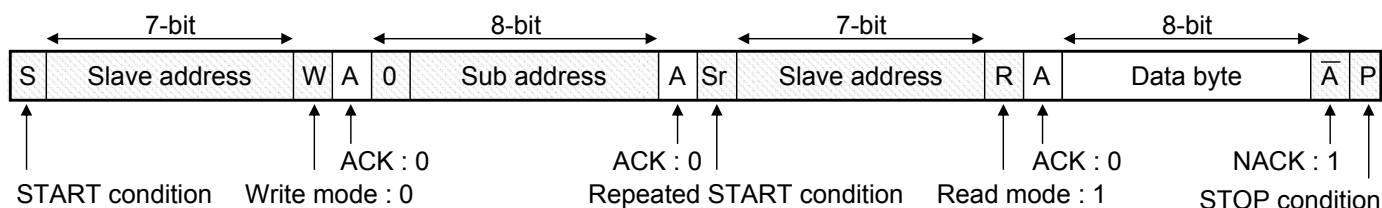
When data is read without assigning the sub address (8-bit), the data of the sub address assigned in the Write mode immediately before is read.



Read mode (In case sub address is specified)

When MSB of sub address (8-bit) is "0", sub address is incremented automatically.

Data byte of specified sub address is read repeatedly continuously until STOP condition is received.

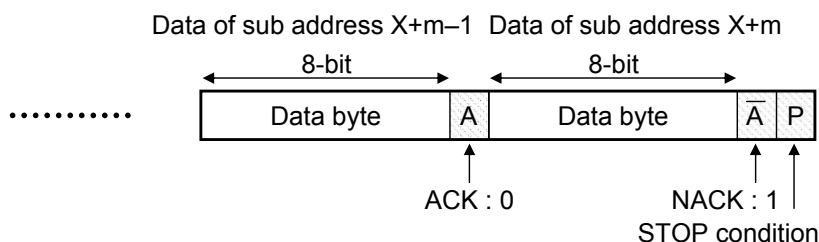
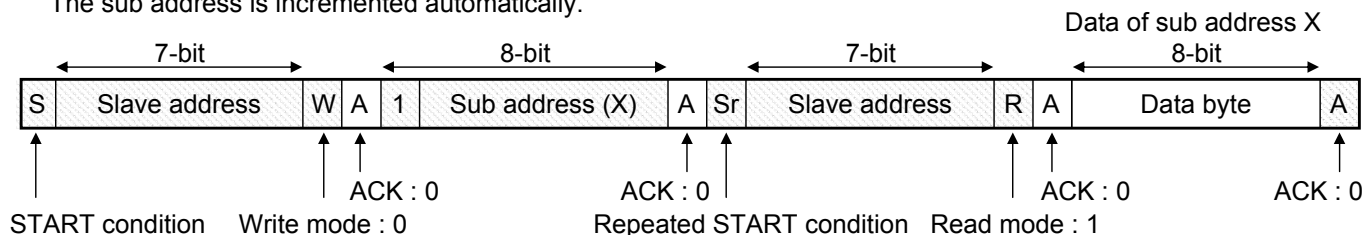




Read mode (Auto increment mode in case sub address is specified)

When MSB of sub address (8-bit) is "1", auto increment mode is specified.

Until STOP condition is received, data byte of sub address incremented automatically by specified sub address can be read continuously

The sub address is incremented automatically.



 : Data transmission from Master
 : Data transmission from Slave

OPERATION (continued)

4. SPI interface

The interface with microcomputer consists of 16-bit serial register (8-bit of command, 8-bit of address), address recorder, and transmission register (8-bit).

Serial interface consists of 4 pins, which are a serial clock pin (SCL), a serial data input pin (SDA), a serial data output pin (SDO [=SLAVE]) and a chip enable input pin (SCE [=GPIO2]).

When SPI interface is used in this LSI, SERSEL pin should be fixed to High-level.

4.1 Reception operation

At MSB first, when SDA is Low at 1st CLK of SCL, Write is recognized.

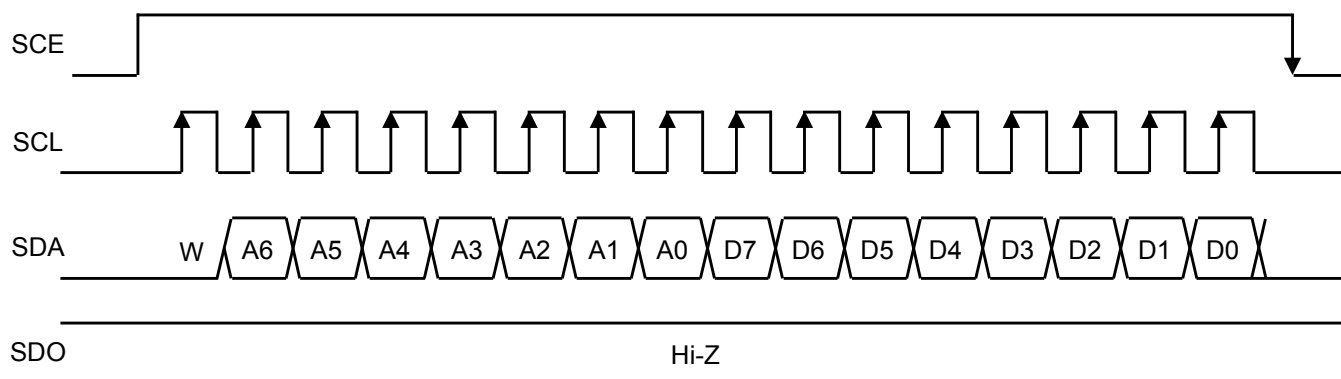
Data is taken into an internal shift register at the rising edge of SCL.

(It is possible to use a maximum frequency of 13 MHz as SCL frequency.)

In High interval of SCE, reception of data becomes ENABLE. (active : High)

Data is transmitted at MSB first in order of control register address (8-bit) and control command (8-bit).

Timing of reception



4.2 Transmission operation

At MSB first, when SDA is High at 1st CLK of SCL, Read is recognized.

Data is taken into an internal shift register at the rising edge of SCL.

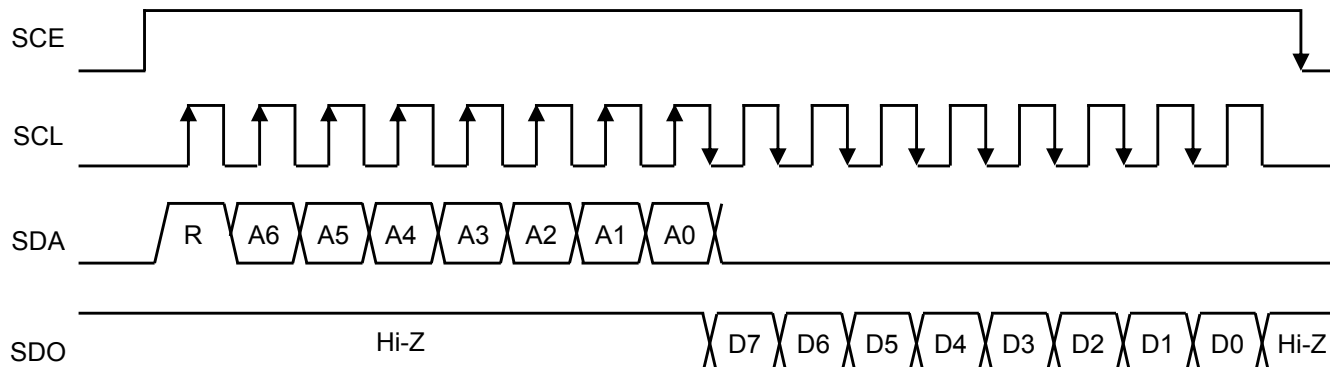
(It is possible to use a maximum frequency of 13 MHz as SC frequency.)

In High interval of SCE, transmission of data becomes ENABLE. (active : High)

Data is transmitted at MSB first in order of control register address (8-bit) and control command (max. 8-bit).

RAM is not read.

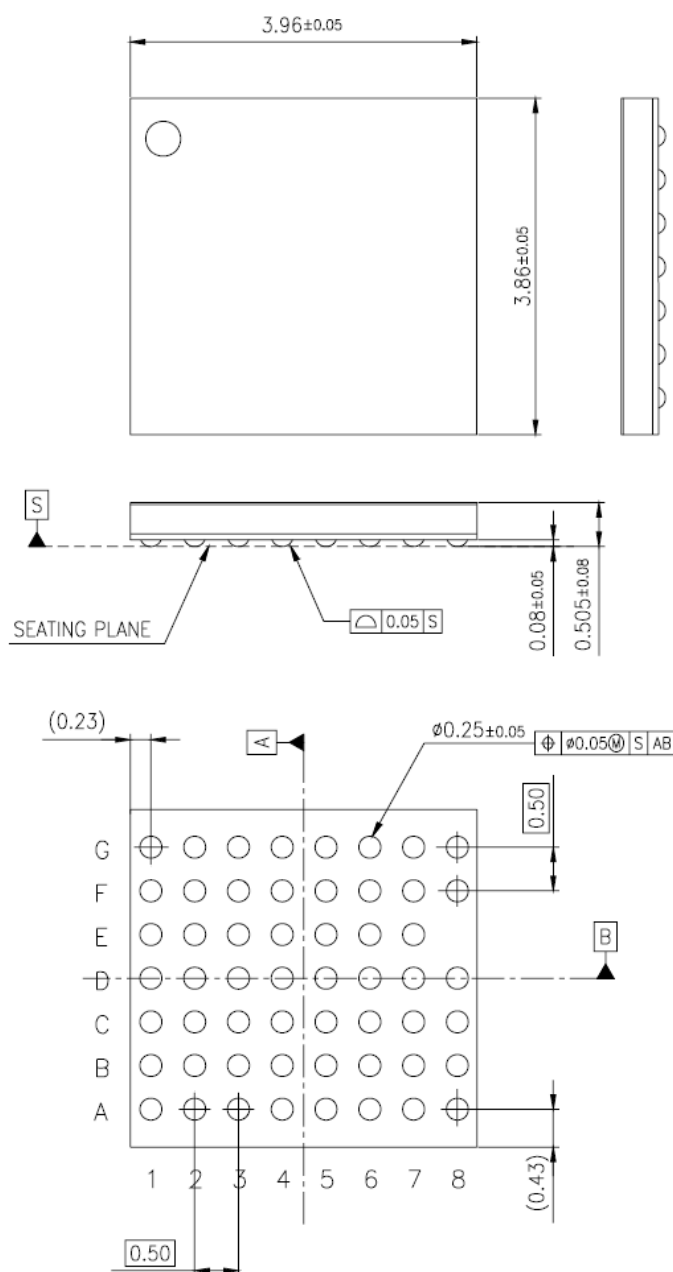
Timing of transmission



PACKAGE INFORMATION (Reference Data)

Package Code : ULGA055-W-3940AKL

Unit:mm



| | |
|------------------|--------------------------|
| Body Material | : Br/Sb Free Epoxy resin |
| Reroute Material | : Cu |
| Bump | : SnAgCu |

IMPORTANT NOTICE

1. When using the LSI for new models, verify the safety including the long-term reliability for each product.
2. When the application system is designed by using this LSI, please confirm the notes in this book.
Please read the notes to descriptions and the usage notes in the book.
3. This LSI is intended to be used for general electronic equipment.
Consult our sales staff in advance for information on the following applications: Special applications in which exceptional quality and reliability are required, or if the failure or malfunction of this LSI may directly jeopardize life or harm the human body.
Any applications other than the standard applications intended.
 - (1) Space appliance (such as artificial satellite, and rocket)
 - (2) Traffic control equipment (such as for automobile, airplane, train, and ship)
 - (3) Medical equipment for life support
 - (4) Submarine transponder
 - (5) Control equipment for power plant
 - (6) Disaster prevention and security device
 - (7) Weapon
 - (8) Others : Applications of which reliability equivalent to (1) to (7) is requiredOur company shall not be held responsible for any damage incurred as a result of or in connection with the LSI being used for any special application, unless our company agrees to the use of such special application.
4. This LSI is neither designed nor intended for use in automotive applications or environments unless the specific product is designated by our company as compliant with the ISO/TS 16949 requirements.
Our company shall not be held responsible for any damage incurred by customers or any third party as a result of or in connection with the LSI being used in automotive application, unless our company agrees to such application in this book.
5. Please use this product in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Our company shall not be held responsible for any damage incurred as a result of our LSI being used by our customers, not complying with the applicable laws and regulations.
6. Pay attention to the direction of LSI. When mounting it in the wrong direction onto the PCB (printed-circuit-board), it might emit smoke or ignite.
7. Pay attention in the PCB (printed-circuit-board) pattern layout in order to prevent damage due to short circuit between pins. In addition, refer to the Pin Description for the pin configuration.
8. Perform visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as solder-bridge between the pins of the semiconductor device. Also, perform full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
9. Take notice in the use of this product that it might be damaged or occasionally emit smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short). Safety measures such as installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply..
10. The protection circuit is for maintaining safety against abnormal operation. Therefore, the protection circuit should not work during normal operation.
Especially for the thermal protection circuit, if the area of safe operation or the absolute maximum rating is momentarily exceeded due to output pin to VCC short (Power supply fault), or output pin to GND short (Ground fault), the LSI might be damaged before the thermal protection circuit could operate.
11. Unless specified in the product specifications, make sure that negative voltage or excessive voltage are not applied to the pins because the device might be damaged, which could happen due to negative voltage or excessive voltage generated during the ON and OFF timing when the inductive load of a motor coil or actuator coils of optical pick-up is being driven.
12. Verify the risks which might be caused by the malfunctions of external components.
13. Due to the unshielded structure of this LSI, functions and characteristics of the product cannot be guaranteed under the exposure of light. During normal operation or even under testing condition, please ensure that the LSI is not exposed to light.
14. Please ensure that your design does not have metal shield parts touching the chip surface as the surface potential is GND voltage.
15. Pay attention to the breakdown voltage of this LSI when using.
More than + 1100 V or less than – 1100 V electrostatic discharge to all the pins might damage this product.

Request for your special attention and precautions in using the technical information and semiconductors described in this book

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- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. We do not guarantee quality for disassembled products or the product re-mounted after removing from the mounting board.
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